

感恩同行 共铸星河

致每一位CSEAC同行者：

刚刚落幕的第十四届CSEAC 2026，汇聚了1400余家全球企业与13.56万人次的行业精英，共同见证了展会规模的历史新高、观众热度的持续高涨与展会规格的全面升级。同期举办的第十四届（2026）中国电子专用设备工业协会半导体设备年会（简称：CEPEA（2026）半导体设备年会），更以其权威性与丰硕成果，为行业交上了满意答卷。

数字背后，是沉甸甸的信任，亦是产业生态的坚韧力量。我们看见了展台前热切的交谈，聆听了论坛上闪耀的真知灼见，更深深感受到了整机与零部件、材料与制造、科研与应用间那股奔涌向前的协同共进之力。

从第一届的拓荒起步，到如今第十五届的千商云集，方寸之地已汇成璀璨的产业星河。CSEAC的每一次择址、每一场圆满，皆因有您的一路相伴。我们以“**专业化、产业化、国际化**”为宗旨，不仅映照了中国半导体产业的成长曲线，更搭建起一座桥梁，让全球智慧在此交汇，让产业力量在此深扎根基。

【展望 · CSEAC 2027】

CSEAC 2027已正式官宣落地苏州国际博览中心。2027年9月1日至3日，金鸡湖畔，我们将以“**芯合力 · 连全球**”的宏大胸怀，再启新程。

愿你我继续携手同行，相聚姑苏，再见真章！

感谢有您，期待再会！

CSEAC 组委会 敬上

Appreciation Letter

To Everyone Who Has Walked This Journey with CSEAC:

The recently concluded 14th CSEAC 2026 brought together more than 1,400 companies from around the world and welcomed 135,600 visits from industry professionals, setting new records in scale, participation, and overall event profile. Held concurrently, the 14th (2026) China Electronic Production Equipment Industry Association Semiconductor Equipment Annual Conference further demonstrated its authority and delivered impressive results, providing a highly satisfactory outcome for the industry.

Behind these figures lies the weight of trust and, even more so, the resilience of our industry ecosystem. We witnessed the enthusiastic discussions at the exhibition booths, heard the insightful perspectives at the forums, and, above all, deeply felt the surging force of collaboration running between complete equipment and parts, between materials and manufacturing, and between research and application.

From the trailblazing beginnings of the first edition to the 15th edition, which brought together thousands of industry professionals—this modest patch of floor has grown into a galaxy of industry. Every milestone CSEAC has reached has been made possible by your continued trust and support. Guided by the principles of **professionalism, industrialization and internationalization**, CSEAC has not only witnessed the growth of China's semiconductor industry, but has also become a platform where global expertise converges, partnerships are forged, and industrial capabilities continue to grow.

【Outlook · CSEAC 2027】

CSEAC 2027 has been officially announced to take place at the Suzhou International Expo Centre. From 1 to 3 September 2027, on the shores of Jinji Lake, we will set out once more with the vision of 'Chips Together · Global Connection'.

May we continue to walk this path together, and create new history.

Thank you for walking this journey with us. We look forward to welcoming you again in Suzhou.

Sincerely,
The CSEAC Organizing Committee

CSEAC 2026 展会报告

CSEAC 2026 Exhibition Report

做强中国芯·拥抱芯世界

Strengthen China's Chips and Embrace the Chip World

第十四届半导体设备材料及核心部件展 (CSEAC 2026)

The 14th Semiconductor Equipment, Materials and Core Parts Exhibition

2026 08.31-09.02

无锡太湖国际博览中心

Taihu International Expo Center, Wuxi, China

组织机构

- **主办单位 Organizers**

风米网-半导体供应链产品平台

Fengm.cn: Semiconductor Supply Chain Product Platform

上海风米云传媒科技有限公司

Shanghai Fengmi Cloud Media Technology Ltd.

- **承办单位 Co-organizers**

风米云(北京)科技会展有限公司

Fengmi Cloud (Beijing) Technology Exhibition Co., Ltd

- **协办单位 Supporting Units**

北方华创科技集团股份有限公司

NAURA Technology Group Co., Ltd.

中微半导体设备(上海)股份有限公司

Advanced Micro-Fabrication Equipment Inc. China (AMEC)

盛美半导体设备(上海)股份有限公司

ACM Research (Shanghai) Inc.

上海微电子装备(集团)股份有限公司

Shanghai Microelectronics Equipment (Group) Co., Ltd. (SMEE)

无锡国家集成电路设计基地有限公司

Wuxi National Integrated Circuit Design Base Co.,Ltd.

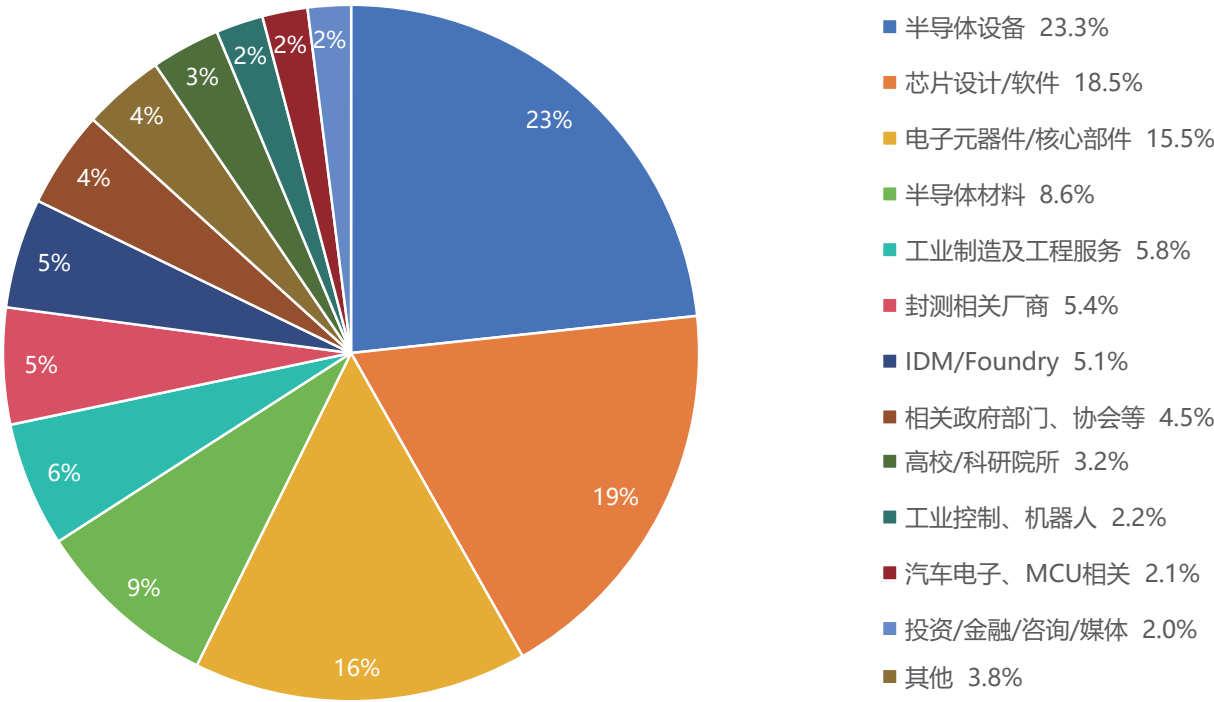
展会数据一览
Data Summary

本届展会累计进场观众 135,633 人次 Total professional visits 135,633	其中港澳台地区、海外观众及国际嘉宾 10,769 人次 Visits from Hong Kong, Macao and Taiwan regions of China & overseas : 10,769
展会相册浏览量 17.3 万 Exhibition photo album views 173,000	展会小程序浏览量 9.2 万 Mini program views 92,000
官方视频号播放量 6.9 万 Official Video Account views 69,000	单场直播累计观看人数 1.1 万 Live stream views 11,000
“逛展打卡”活动累计参与人次 1.2 万 “Check-in & Explore” activity participants 12,000	校企专区活动人次 0.57 万 Academia Industry Zone participants 5,700

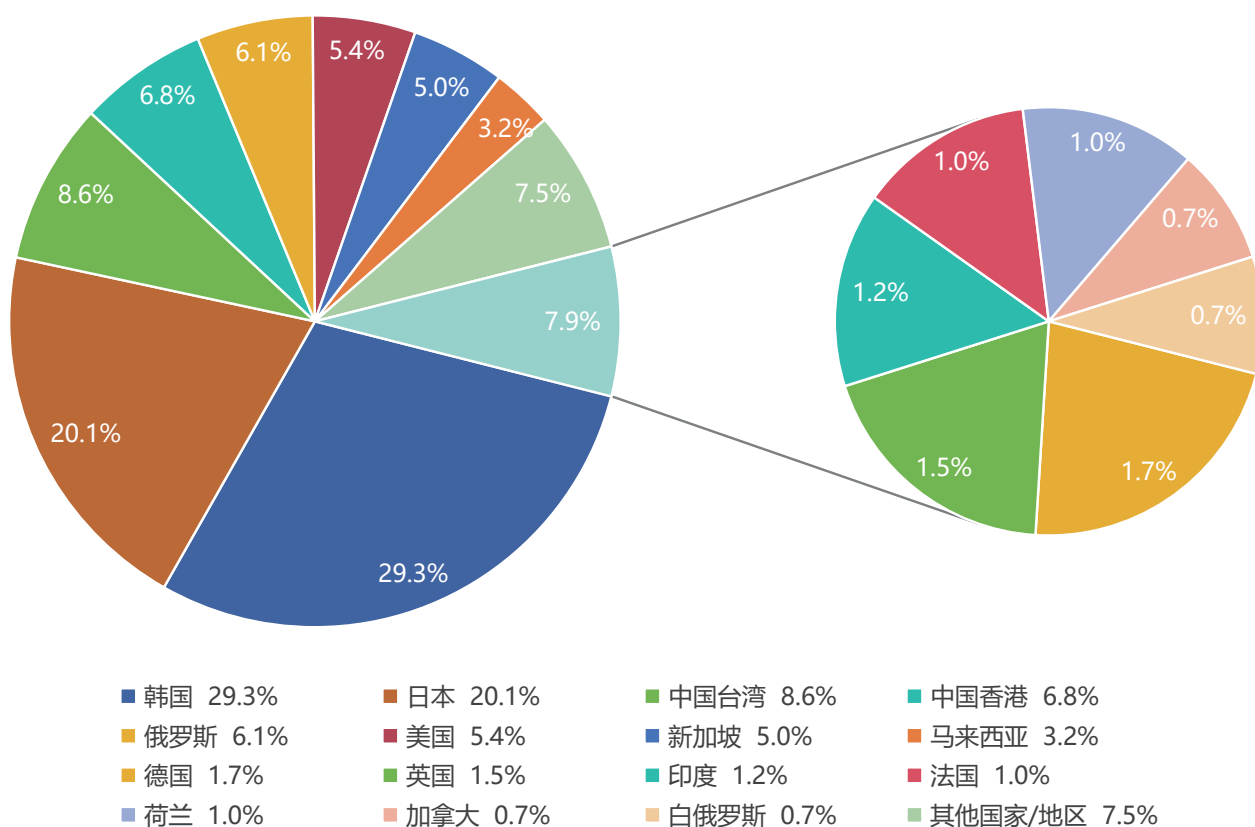
*以上数据收集时间范围为8月31日00:00至9月2日24:00
*Data period: Aug 31 (00:00) – Sep 2 (24:00)

展会数据图
Exhibition Data Charts

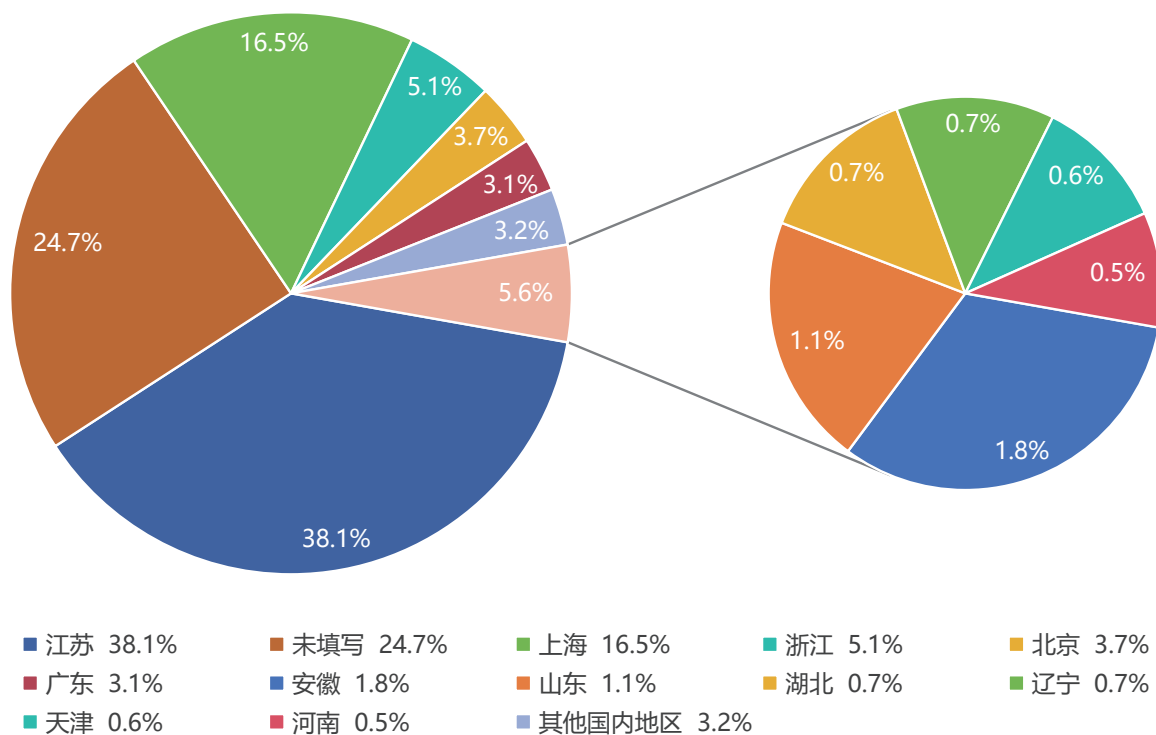
1.观众行业分析
Visitor Industry Analysis



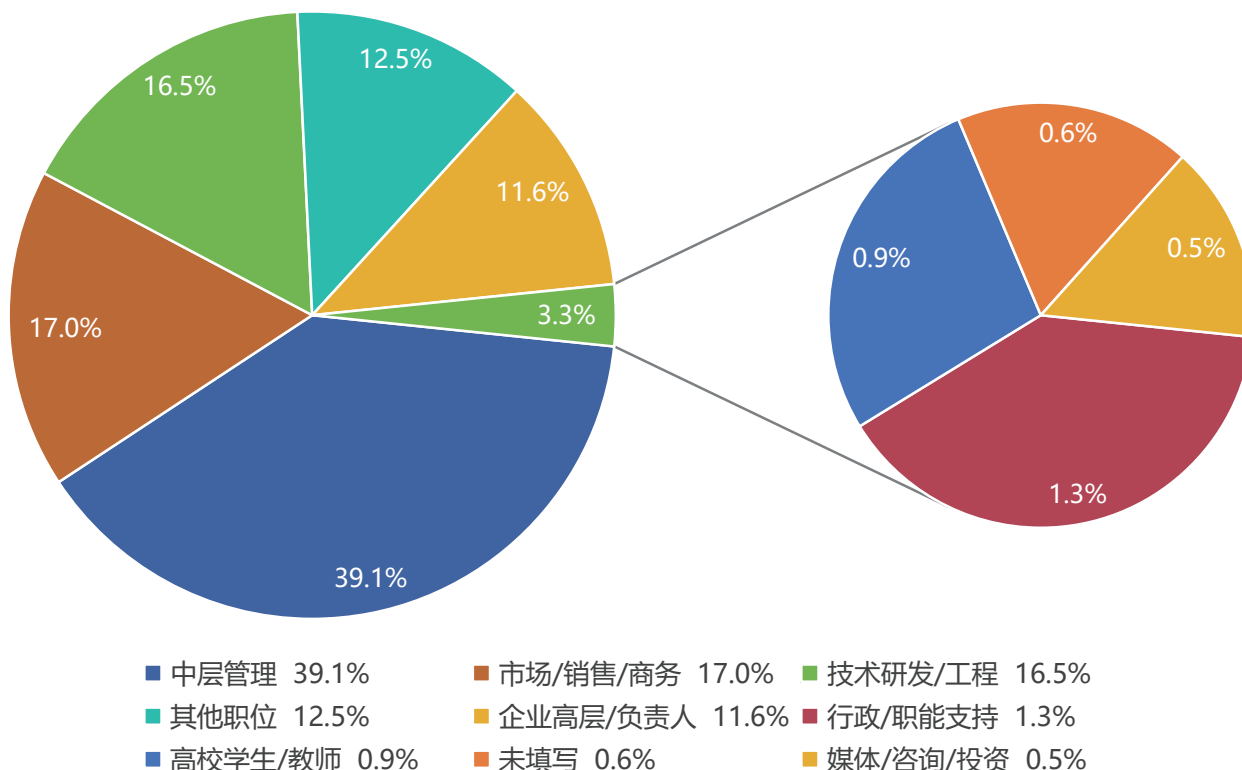
2.观众地域来源(国际) Visitor Geographic Origins (International)



3.观众地域来源(国内) Visitor Geographic Origins (Domestic)



4.观众职位画像 Visitor Job Role Profile



— CSEAC 2026亮点回顾 — Highlights of CSEAC 2026

● 第十四届展会, 再创纪录 A Record-Setting 14th Edition

第十四届半导体设备材料及核心部件展（CSEAC 2026），来自全球超过25个国家和地区的产业链企业**1,400**余家，累计接待专业观众**135,633**人次，见证了CSEAC的规模再创新高、观众热度持续高涨、展会规格大幅提升，同期举办的设备年会权威性与成效有目共睹。

The 14th China Semiconductor Equipment, Materials and Core Parts Exhibition (CSEAC 2026) brought together more than 1,400 enterprises from across the semiconductor value chain, drawn from over 25 countries and regions worldwide, and welcomed a cumulative total of 135,633 professional visits. The numbers told the story: a record-shattering scale, sustained visitor momentum, and a meaningful step up in the exhibition's stature, while also demonstrating the authority and effectiveness of the concurrently held equipment industry annual conference.



● 江苏省省长亲临CSEAC展会现场巡馆指导 Opening Day – Leadership Visits

开幕首日，江苏省省长刘小涛、副省长沈剑荣，工信部电子信息司副司长郭力力，无锡市委书记杜小刚、市长蒋锋等省市及主管部门领导亲临 CSEAC现场考察指导。

On the Opening Day, the show was honored by the presence of provincial and ministerial leaders, who toured the floor and offered on-site guidance: Liu Xiaotao, Governor of Jiangsu Province; Shen Jianrong, Vice Governor of Jiangsu Province; Guo Lili, Deputy Director General of the Electronic Information Department, Ministry of Industry and Information Technology (MIIT); Du Xiaogang, Party Secretary of Wuxi; and Jiang Feng, Mayor of Wuxi.



● 国内外龙头企业齐聚!本届展会集结半导体全链力量 Industry Leaders Rally the Full Chain

国内外龙头企业集结半导体全链力量，北方华创、中微、盛美、拓荆、上微、中国电科、芯源微、凯世通、中科飞测、微导纳米、先导集团、日联、东方晶源、屹唐、中安、富创精密、江丰电子、新莱应材、英杰电气、科百特、珂玛科技等国内龙头及产业链优质企业，与迪思科、TEL、杜邦、徕卡、尼康、莱宝、光驰、SMC、ACS、纳科鑫、日立高新、马波斯、基恩士、富士胶片、埃地沃兹、林德中国、空气产品公司、菲尼克斯、HORIBA、阿自倍尔等国际巨头同台“献艺”。

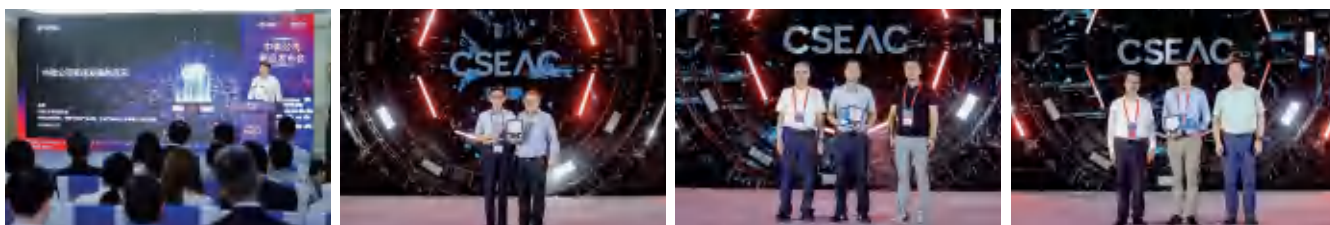
Industry leaders from home and abroad rallied the full strength of the semiconductor chain. On the Chinese side were flagship players and high-quality supply-chain partners including NAURA, AMEC, ACM Research, Piotech, SMEE, the 45th Research Institute of CETC, VeriSilicon, Kingstones, Skyverse, Leadmicro, Vital Group, Unicom Technology, DJEL, E-Town Semiconductor, ZAS, Fortune Precision, Konfoong Materials, Kinglai Group, Injet Electric, Cobetter and Kema Technology. Global heavyweights such as DISCO, Tokyo Electron (TEL), DuPont, Leica, Nikon, Leybold, Oporun, SMC, ACS, NaKoxin, Hitachi High-Tech, Marposs, KEYENCE, Fujifilm, Edwards, Linde China, Air Products, Phoenix Contact, HORIBA, and Azbil also share the same stage with them.



● 新品集中亮相, 两大创新奖项重磅揭晓 Debut Equipment and Innovation Awards

中微公司携六款高端设备首发亮相，包括刻蚀、薄膜、MOCVD等关键工艺设备；首次举办的“CSEAC 产品创新奖”与“CSEAC 技术创新大奖”的揭晓，破纪录的逾百人规模的组团观展，都汇聚着产业发展活力。

AMEC unveiled six high-end tools in their debut appearances, spanning key process equipment including etching, thin-film deposition, and MOCVD systems. The inaugural CSEAC Product Innovation Award and Grand Award for Technological Innovation — together with a record-breaking delegation visit of more than one hundred participants — came together as a vivid testament to the vitality of the industry.



● 20余场专业论坛, 汇聚产业发展智慧 The 14th Semiconductor Equipment Annual Conference

展会同期举办专业论坛、闭门会议及交流活动等20余场，带来200余个专业报告，形成覆盖宏观趋势、技术路线、供应链协同、先进制造、产学研合作和人才发展的多层次论坛矩阵。

同期的第十四届（2026）中国电子专用设备工业协会半导体设备年会，以“链动新征程，数智赋芯能”为主题，多位行业大咖和产业精锐发表演讲，现场人气鼎盛；并行的多场专题技术论坛，场场爆满，业界反响热烈。

Under the theme "Chain-driven New Journey · Digital Intelligence Empowering Chips," the 14th (2026) Semiconductor Equipment Annual Conference of the China Electronic Production Equipment Industry Association (CEPEA) brought together a distinguished lineup of industry leaders and senior voices. The chemical reaction between exhibition and conference — "exhibition plus forum" — was felt viscerally by every CSEAC participant.



- **全球25个国家和地区参与, 大咖云集, 资源互通**
300+ Overseas and Foreign-Invested Enterprises, 25 Countries

300余家海外及外资企业，来自美国、韩国、日本、德国、俄罗斯、新加坡、马来西亚、瑞士、爱尔兰、西班牙、阿联酋迪拜、摩洛哥、意大利等25个国家和地区的国际资源在CSEAC加速连接、互通。展会同期举办的半导体产业CEO论坛，集结了全球半导体行业领军企业家与高管。牛津经济研究院亚太首席经济学家卢姿蕙、Yole集团副总裁Gary Huang、中国工程院外籍院士奥泰因·赫尔佐格等国际权威专家带来权威报告分享；俄罗斯首次由工贸领域代表团专程参与迈向自主可控的半导体制造之路论坛等，都是对CSEAC专业度与市场影响力的肯定。

More than 300 overseas and foreign-invested enterprises from 25 countries and regions — including the United States, the Republic of Korea, Japan, Germany, Russia, Singapore, Malaysia, Switzerland, Ireland, Spain, Dubai (UAE), Morocco, and Italy — converged at CSEAC, accelerating the connection and two-way flow of international resources.

Running in parallel, the Semiconductor Industry CEO Forum convened industry leaders and senior executives from around the globe. Louise Loo, Asia-Pacific Chief Economist at Oxford Economics; Gary Huang, Vice President of Yole Group; and Otthein Herzog, Foreign Member of the Chinese Academy of Engineering — among other internationally recognized authorities — delivered authoritative keynote reports. A further first: Russia dispatched a dedicated trade-and-industry delegation to take part in the Forum on the Path to Sovereign Semiconductor Manufacturing. Each milestone was, in its own way, a clear endorsement of CSEAC's professional depth and market influence.



- **供需对接, 让洽谈走向务实合作**
Supply-Demand Matchmaking

供需对接，聚焦半导体设备、材料及核心零部件研发端与应用端需求，共计86家海内外供需企业进场洽谈。模式高效、氛围轻松，得到参与企业的一致好评。

The Supply-Demand Matchmaking program zeroed in on the R&D-side and application-side needs of semiconductor equipment, materials, and core components, drawing 86 supply-and-demand enterprises from home and abroad to the negotiation floor. Its efficient format and relaxed atmosphere earned unanimous praise from the participating companies.



● 120+校企联动, 贯通成果转化与人才对接 "Fengmi Human Resources" — 120+ University-Industry Linkages

“风米人力行”的120+校企联动，贯通成果转化与人才对接：清华大学、复旦大学、西安电子科技大学、东南大学等近30所重点高校及科研院所，通过成果展示、技术发布和校企交流等形式，推动高校创新资源与企业实际需求精准对接，校企专区累计展示高校科研成果50余项。

“高校产学研成果路演”汇聚上海交通大学、浙江大学、复旦大学、山东大学、华东理工大学、江西理工大学、中国科学院宁波材料技术与工程研究所等16支高校科研团队。

在“企业人才招聘区”，北方华创、中微公司、拓荆科技、LAM、TEL等国内外行业龙头及近百家优质企业集中发布500余个岗位需求。

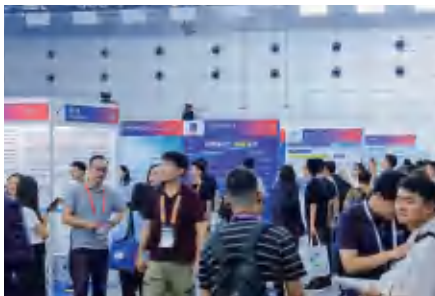
Under the initiative "Fengmi Human Resources", 120+ university-industry collaborations bridged commercialization of research outcomes with talent matchmaking. Nearly 30 leading universities and research institutes — among them Tsinghua University, Fudan University, Xidian University, and Southeast University — engaged through achievements showcases, technology releases, and university-industry dialogues, channeling academic innovation into real industry needs. The university-industry zone cumulatively presented over 50 research outcomes from academia.

Industry-University-Research Roadshow

The Industry-University-Research Roadshow brought together 16 academic research teams from Shanghai Jiao Tong University, Zhejiang University, Fudan University, Shandong University, East China University of Science and Technology, Jiangxi University of Science and Technology, and the Ningbo Institute of Materials Technology and Engineering of the Chinese Academy of Sciences, among others.

Enterprise Talent Recruitment Zone — 500+ Open Positions

At the Enterprise Talent Recruitment Zone, NAURA, AMEC, Piotech, Lam Research, Tokyo Electron, and nearly 100 other leading and quality enterprises — both domestic and international — collectively released more than 500 job openings.



● 千人晚宴共祝产业盛典

A thousand-guest banquet celebrates the industry's grand event.



一次专业展会，一场生态协同

CSEAC 2026以展览为载体，形成“一展多效”的服务体系，所汇聚的正是推动产业向前发展的多元力量。当前，人工智能、高性能计算、智能汽车等新兴应用持续拓展半导体产业的发展空间，同时也对设备、材料和核心零部件的技术性能、供应能力及协同效率提出更高要求，这更需要整机、零部件、材料、制造、科研、应用和资本等多方共同参与。

CSEAC将继续坚持专业化、产业化、国际化发展方向，与全球半导体产业同仁汇聚苏州，在CSEAC 2027上再见真章！

Built around the exhibition as its anchor, CSEAC has shaped a "one show, multiple effects" service system — bringing together the diverse forces propelling the industry forward.

Today, the rise of emerging applications — from AI and high-performance computing to smart vehicles — continues to expand the frontier of the semiconductor industry, while at the same time raising the bar on the technical performance, supply capability, and collaborative efficiency of equipment, materials, and core components. Meeting these new demands will require the joint participation — and tight coordination — of system integrators, component suppliers, materials providers, manufacturers, research institutes, application leaders, and capital.

CSEAC will continue to advance along the path of professionalism, industrialization, and internationalization. Together with our semiconductor-industry peers from around the world, we will reconvene in Suzhou and make new history at CSEAC 2027!

第15届国际半导体设备材料及核心部件博览会（CSEAC CHINA 2027）

主题：芯合力·连全球

展期定为：2027年9月1日-3日

地点：苏州国际博览中心！

The 15th International Semiconductor Equipment, Materials, and Core Parts Expo (CSEAC CHINA 2027)

Theme: Chips Together, Global Connection

Dates: September 1–3, 2027

Venue: Suzhou International Expo Center

— 观众活动回顾 — On-Site Visitor Activities Recap

● 打卡领礼 Check-in & Explore For Rewards

观众通过小程序对照展位地图，走到哪里扫哪里，掌上完成、高效逛展。观众在打卡过程中发现企业、了解产品、产生交流。把“路过展位”变成“走进展位”，把“匆匆一瞥”变成“有效停留”。“打卡探馆·芯动之旅”最终累计打卡人次达**1.2万**。

Using a mini-program and the exhibition map, visitors could scan QR codes as they moved through the venue, enabling an efficient, mobile-friendly browsing experience. The check-in process encouraged visitors to discover companies, learn about products, and engage in interactions—transforming casual passersby into booth visitors and turning fleeting glances into meaningful engagement. The "Check-in & Explore: A Journey into the World of Chips" campaign ultimately recorded a total of 12,000 check-ins.



● 免费清凉补给 Free Cooling Refreshments

逛CSEAC 2026是体力活。在论坛间隙、在展馆穿梭途中，小小冰饮为参观参会者提供大大能量。“补给点”吸引不少参会观众驻足参与，活动得到逛展观众的一致好评。

CSEAC 2026 takes energy! Chilled drinks recharge attendees between forum sessions and hall walks. The refreshment stations were well-visited and well-received by exhibition visitors.



● 定点定时抽奖 Scheduled Draws: Win Great Gifts on the Spot

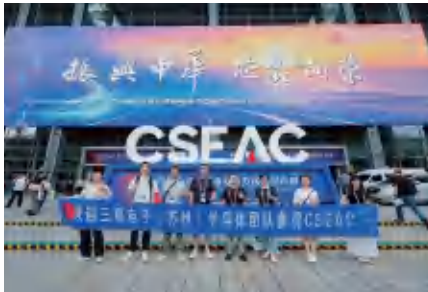
指定展商展位定时抽奖，大疆Osmo Pocket 4、华为手表GT 6、磁吸移动电源等大奖依次开出，活动现场热度极高，人声鼎沸。参与展商对活动的配合度超预期，主动加码准备企业品牌周边礼品。展商、观众均对该活动连连褒赞。

Timed lucky draws took place at selected exhibitor booths. Top prizes such as the DJI Osmo Pocket 4, HUAWEI Watch GT 6 and magnetic power banks were given out. The event drew massive crowds. Exhibitors exceeded expectations by adding extra branded giveaways. The activity won wide praise from exhibitors and visitors alike.



- **观众成团同行**
Group Visitor Delegations

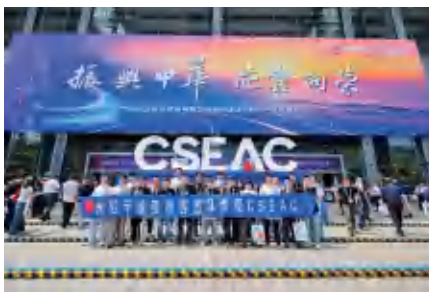
本次展会共7支专业观众组团赴会，其中规模最大团人数超百人。
Seven professional visitor delegations attended the show, with the largest group exceeding 100 participants.



三星电子(苏州)半导体有限公司
Samsung Electronics (Suzhou) Semiconductor Co., Ltd.



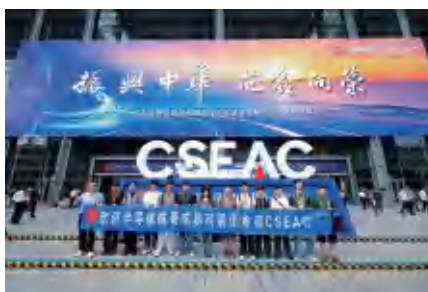
西诺斯(西安)洁净技术有限公司
CINOS(Xi'an) Clean Technology Co., Ltd.



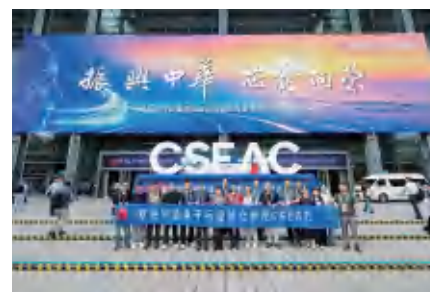
宁波亚德客自动化工业有限公司
Ningbo Airtac Automatic Industrial Co., Ltd.



江苏杰玛森半导体科技有限公司
Jiangsu Jiemasen Semiconductor Technology Co., Ltd.



半导体求职观展团
Semiconductor Career-Seeking Visitor Delegation



宁波电子行业协会代表团
Ningbo Electronic Industry Association Delegation

宜兴陶瓷产业园区代表团
Yixing Ceramic Industrial Park Delegation

— 同期论坛回顾 —
Concurrent Forum Recap

第十四届（2026年）中国电子专用设备工业协会半导体设备年会
The 14th (2026) CEPEA Semiconductor Equipment Annual Conference



● 嘉宾风采
Speakers



《AI 引领半导体装备新未来：北方华创的发展战略与前瞻探索》
AI Pioneers the Next Era of Semiconductor Equipment: NAURA's Strategy and Prospective Initiatives

董博宇 中国电子专用设备工业协会理事长 / 北方华创科技集团股份有限公司CEO
Dong Boyu, Chairman, China Electronic Production Equipment Industry Association, CEO of NAURA Technology Group Co., Ltd.



崔荣国 无锡高新区党工委书记、
无锡市新吴区委书记
Cui Rongguo, Secretary of the Party Working Committee of Wuxi National Hi-Tech District (WND) and Secretary of the CPC Xinwu District Committee of Wuxi



左雷 中国电子科技集团有限公司总监
Zuo Lei, Director of China Electronics Technology Group Corporation (CETC)



主持人: 王志越 中国电子专用设备工业协会秘书长
Moderator: Wang Zhiyue, Secretary-General, China Electronic Production Equipment Industry Association



《量子科技体系和产业体系建设》
Construction of the quantum technology and industrial system
陆军 中国电子科技集团公司首席科学家
Lu Jun, Chief Scientist, China Electronics Technology Group Corporation



《三维闪存架构工艺设备的协同创新与发展》
Synergistic Innovation and Development of 3D NAND Flash Architecture, Process and Equipment

冯耀斌 长江存储科技有限责任公司研发副总经理
Feng Yaobin, Vice President of R&D, Yangtze Memory Technologies Co., Ltd.



《构建半导体具身智能设备开发范式平台, 实现合作共赢》

Building a Development Paradigm for Embodied-Intelligence Semiconductor Equipment: Enabling Win-Win Collaboration

黎家俨 合肥晶合集成电路股份有限公司研发AI总负责人
Chiayen Li, Head of AI R&D, Nexchip Semiconductor Corporation



《构建半导体具身智能设备开发范式平台, 实现合作共赢》

Building a Development Paradigm for Embodied-Intelligence Semiconductor Equipment: Enabling Win-Win Collaboration

杨洋 北京北方华创微电子装备有限公司软件体系总经理
Yang Yang, General Manager, Software System, Beijing Naura Microelectronics Equipment Co., Ltd.



主持人: 张帆博士/教授 中国电子专用设备工业协会副理事长 日联科技集团股份有限公司研究院院长

Moderator: Professor/Dr. Zhang Fan, Vice Chairman of China Electronic Production Equipment Industry Association, Director of Research Institute of Unicom Technology (Group) Co., Ltd.



《芯片制造量检测设备现状与国产化进程》
The current situation and localization progress of equipment for IC fabrication metrology and inspection

李晋湘 中国电子专用设备工业协会副秘书长、工信部电子科技委专家委员
Li Jinxiang, Executive Deputy Secretary general of China Electronic Production Equipment Industry Association & Member of the Electronic Science and Technology Committee, MIIT



《元夫先进封装减薄和切割工艺解决方案》
Yuanfu Advanced Packaging Thinning and Dicing Process Solution

郭谦 江苏元夫半导体科技有限公司副总经理
Chien Kuo, VP of sales, Leadlap Semiconductor



《从“看见”到“预见”——电子束量检测设备与计算光刻的协同演进与未来趋势》

From Seeing to Predicting
—Synergistic Evolution and Future Trends of e-Beam Metrology & Inspection and Computational Lithography

雒晓军 东方晶源微电子科技(北京)股份有限公司高级副总裁
Luo Xiaojun, SVP, Dongfang Jingyuan Electron CO., LTD.

- 企业新品发布专场
Enterprise New Product Launch Session



江苏微导纳米科技股份有限公司:iTomic® MeT 系列原子沉积系统、iTronix® MTP 系列等离子体增强化学气相沉积系统发布
Jiangsu Leadmicro Nano-Technology Co.,Ltd. Releases iTomic® MeT Atomic Layer Deposition (ALD) System and iTronix® MTP Plasma Enhanced Chemical Vapor Deposition (PECVD) System



江苏京创先进电子科技有限公司:JTA-9612全自动减薄抛光贴撕膜一体设备发布
Jiangsu JCA Electronic Technology Co., Ltd. Releases JTA-9612 Fully Automatic Grinding, Polishing and Moulder In-line System

江苏快克芯装备科技有限公司:先进封装热压键合设备 (TCB) 发布
Quick Semiconductor Technology Co.,Ltd. Releases Advanced Packaging Thermal Compression Bonding (TCB) Equipment



● 嘉宾风采 Speakers



《AI 浪潮重塑半导体格局:先进工艺革新与盛美差异化创新之路》

The AI Revolution Reshaping the Semiconductor Industry: Advanced Process Innovation and ACM's Differentiated Innovation Strategy

金一诺 盛美半导体设备(上海)股份有限公司工艺副总裁
Jin YINUO, Vice President of Process Technology, ACM Research (Shanghai), Inc.



《从“能检”到“能替”:无图形颗粒检测设备基线匹配的技术纵深与实践》

From "Usable" to "Replacement": Baseline Matching for Unpatterned Wafer Inspection

初新堂 京城中安半导体设备(北京)有限公司市场副总
Seddy CHU, Marketing VP, Jingcheng Zhongan Semiconductor Equipment (Beijing) Co., Ltd.



《2026上半年中国半导体设备行业经济定性分析》

China Semiconductor Equipment Industrial Sector Analysis for the First Half of 2026

王志越 中国电子专用设备工业协会秘书长
Wang Zhiyue, Secretary-General, China Electronic Production Equipment Industry Association

● 董事长圆桌对话 Chairmen Roundtable Discussion

从替代到引领:中国半导体设备的下一程

From Substitution to Leadership: The Next Chapter of China's Semiconductor Equipment Industry



圆桌对话

主持人:

张卫 上海复旦微电子集团股份有限公司董事长兼总经理

嘉宾:

董博宇 中国电子专用设备工业协会理事长/北方华创科技集团股份有限公司CEO

丛海 中微半导体设备(上海)股份有限公司资深副总裁、全球业务管理部、等离子刻蚀产品总部、外延产品及介质薄膜产品部总经理

郑志成 合肥晶合集成电路股份有限公司联席总经理

于大全博士 厦门云天半导体科技有限公司董事长兼总经理

蔡琳 北京华峰测控技术股份有限公司总经理

辛晨 日联科技集团股份有限公司董事会秘书

Roundtable Dialogue

Moderator:

Zhang Wei, Chairman and General Manager, Shanghai Fudan Microelectronics Group Co., Ltd.

Guest:

Dong Boyu, Chairman, China Electronic Production Equipment Industry Association, President of NAURA Technology Group Co., Ltd.

Hai Cong, Senior VP, Global Business Management, General Manager of Etch PBG, EPI and PECVD Division, Advanced Micro-Fabrication Equipment Inc. China (AMEC)

Mark Zheng, Co-President, Nexchip Semiconductor Corporation

Yu Daquan, Chairman & CEO, Xiamen Sky Semiconductor Technology Co., Ltd.

Linda Cai, CEO, Beijing Huafeng Test & Control Technology Co., Ltd.

Xin Chen, Secretary of the Board, Unicomp Technology (Group) Co., Ltd.

刻蚀技术、制程及设备专题论坛 Seminar on Etching Technology, Processes and Equipment



● 嘉宾风采 Speakers



主持人:丛海 中微半导体设备(上海)股份有限公司资深副总裁、全球业务管理部、等离子刻蚀产品总部、外延产品及介质薄膜产品部总经理

Moderator: Hai Cong, Senior VP, Global Business Management, General Manager of Etch PBG, EPI and PECVD Division, Advanced Micro-Fabrication Equipment Inc. China (AMEC)



《中微公司: 精进刻蚀技艺, 决胜三维工艺》
AMEC: Mastering Etch Technology, Excelling in 3D Processes

王红超 中微公司刻蚀市场开拓及技术营销副总监
Tony Wang, Associate Director of Etch BD & Tech Marketing



《多平台刻蚀能力建设与量产实践》
Building Multi-Platform Etch Capability for Mass Production

陈颖儒 重庆芯联微电子有限公司 刻蚀工程处副总监
Terry Chen, Deputy Director of Etching Engineering Department, Chongqing Xinlian Microelectronics Co., Ltd



《邑文科技刻蚀技术在三代半硅光化合物半导体领域的应用》
Application of AMTE Etching Technology in the Field of Third-Generation Silicon Photonic Compound Semiconductors

邓家亮 无锡邑文微电子科技股份有限公司销售部总经理
Bill Deng, Sales General Manager, Advanced Materials Technology & Engineering Co., Ltd



《离子束修平在表面超平坦化与梯度刻蚀的应用》
Ultra-flat Surface and Gradient Etching for Advanced Application Using Ion Beam Trimming

李自超 江苏鲁汶仪器股份有限公司技术专家
Zichao Li, Technical Expert, Jiangsu Leuven Instruments Co., Ltd



《面向高端硅光子芯片制造的前沿尖端解决方案》
Cutting-edge Solutions for Advanced SiPho Chip Manufacturing

陈才干 泛林集团 工艺经理
Chris Chen, Process Manager, Lam Research

● 圆桌对话
Roundtable Discussion



圆桌对话

主持人:

李海明 重庆芯联微电子有限公司资深副总经理

嘉宾:

刘志强 中微半导体设备(上海)股份有限公司 集团副总裁,
CCP刻蚀产品事业部总经理

卢合强 华海清科股份有限公司 离子注入工艺技术总监

董溯 江苏鲁汶仪器股份有限公司 副总经理

王旭 御微半导体 地区部总经理

Roundtable Dialogue

Moderator:

Herman Lee, Senior Vice President, Chongqing Xinlian Microelectronics Co., Ltd.

Guest:

Zhiqiang Liu, Group Vice President, GM of CCP Etch Product Division,
Advanced Micro Fabrication Equipment Inc. China (AMEC)

Jack Lu, Director of Ion Implant Process Technology, Hwatsing Technology Co., Ltd.

Su Dong, Deputy General Manager, Jiangsu Leuven Instruments Co., Ltd

Xander Wang, Regional General Manager, Yuwei Semiconductor Technology Co., Ltd

薄膜沉积技术、制程及设备专题论坛

Seminar on Thin-Film Deposition Technology, Processes and Equipment



● 嘉宾风采 Speakers



主持人:于大洋 北京诺华资本投资管理有限公司 总经理

Moderator: Alex Yu, General Manager, Beijing NUO Capital Investment Management Co., Ltd



《先进逻辑与存储器件半导体装备应用与挑战》

Application and Challenges of Semiconductor Equipment for Advanced Logic and Memory Devices

许灿 中微半导体设备(上海)股份有限公司金属沉积产品部总经理

Can Xu, GM of metal product division, Advanced Micro-Fabrication Equipment Inc. China



《集成电路制造中金属化工工艺装备的应用与挑战》

Metallization Equipment in IC Manufacturing: Applications and Challenges

张钦彤 北京北方华创微电子装备有限公司 MDP事业单元CTO

Qintong Zhang, MDP BU CTO, Beijing NAURA Microelectronics Equipment Co., Ltd.



《超保形性介电材料原子层沉积工艺 - 助力国产三维芯片技术开发和应用》

Advanced Conformal Dielectric-Material Atomic Layer Deposition (ALD) for 3D-IC Technology Development and Applications

刘武平 拓荆科技(上海)有限公司副总裁
Wuping Liu, PhD, Vice President, Piotech (Shanghai) Co., Ltd



《面向晶圆制造的前道关键装备:从原子层沉积到离子注入的协同创新》

Key Front-End Equipment for Semiconductor Processing: Collaborative Innovation from Atomic Layer Deposition to Ion Implantation

张丛 青岛思锐智能科技股份有限公司首席技术官

Cong Zhang, CTO, Qingdao SRI Intellectual Technology Co., Ltd



《算力换产能—AI驱动半导体设备与制造的效能革命》

Computing Power for Capacity: AI - Driven Efficiency Revolution in Semiconductor Equipment & Manufacturing

吴启明 合肥晶合集成电路股份有限公司资深处长

Ryan Wu, Senior Director, Nexchip Semiconductor Corporation



《High-k材料在逻辑器件的应用》
Applications of High-k Materials in Logic Semiconductor Devices

符腾飞 江苏微纳科技股份有限公司
专家工程师
Tengfei Fu, Expert Engineer, Jiangsu Leadmicro Nano-Technology Co., Ltd



《半导体薄膜设备国产化新进展》
New Progress in Domestic Production of Semiconductor Thin Film Equipment

张汀 上海积塔半导体有限公司总经理助理
Ting Zhang, General Manager Assistant
, GTA Semiconductor Co., Ltd.



《集成电路物理气相沉积设备研发与产业化》
R&D and Industrialization of Physical Vapor Deposition Equipment for Integrated Circuits

程厚义 合肥致真精密设备有限公司董事长/
首席技术官
Houyi Cheng, Chairman / CTO, Truth Equipment Co., LTD



《面向亚3纳米节点的集成电路原子级制造技术矩阵》
Atomic-Level Manufacturing Technology Matrix for Sub-3nm Node Integrated Circuits

金一诺 盛美半导体设备(上海)股份有限公司
工艺副总裁
Yinuo Jin, Vice President of Process Technology, ACM Research (Shanghai), Inc.

● 圆桌对话 Roundtable Discussion



圆桌对话

主持人：

于大洋 北京诺华资本投资管理有限公司 总经理

嘉宾：

吴启明 合肥晶合集成电路股份有限公司资深处长

邓斌 北京北方华创微电子装备有限公司MDP事业单元总经理

蒋剑勇 宁波江丰电子材料股份有限公司半导体事业部总经理

汪穹宇 安徽安德科铭半导体科技股份有限公司董事长/总经理

李杰 埃克斯控股(北京)有限公司董事长

Roundtable Dialogue

Moderator:

Alex Yu, General Manager, Beijing NUO Capital Investment Management Co., Ltd

Guest:

Ryan Wu, Senior Director, Nexchip Semiconductor Corporation

Bin Deng, General Manager, NAURA MDP Business Unit

Ronnie Jiang, GM, Semiconductor BU, Konfoong Materials International Co., Ltd.

Qiongyu Wang, Chairman/CEO, Anhui ADChem Semi-Tech. Co., Ltd.

Jie Li, Chairman, IKAS Holding (Beijing) Co., Ltd.

量测技术及设备专题论坛

Seminar on Measurement Technology and Equipment



● 嘉宾风采 Speakers



主持人:季宗亮 季华资本创始人、启泰沣华创始人
Moderator: Zongliang Ji, Founder of Jihua Capital & ChiptestX



黄安君 华虹半导体(无锡)有限公司副总裁, 无锡市半导体行业协会秘书长
Anjun Huang, Vice President of Hua Hong Semiconductor (Wuxi) Co., Ltd. & Secretary-General of Wuxi Semiconductor Industry Association



《晶圆与裸片级光学故障定位难点及技术路线图》
Wafer and Die Level Optical Fault Localization Challenges and Roadmap
潘福杰 赛美康半导体(无锡)有限公司董事长兼首席执行官
Julian Pan, Chairman & Chief Executive Officer, SEMICAPS China



《东京精密 (Accretech) 三维封装工艺及散热技术专项技术更新》
Accretech technical update for 3D package process and heat dissipation technology
白建星 东精精密设备(上海)有限公司市场部
Jianxing Bai, Marketing Planning & Information Dept, ACCRETECH (CHINA) CO., LTD



《东京精密 (Accretech) 三维封装工艺及散热技术专项技术更新》
Accretech technical update for 3D package process and heat dissipation technology
陆振洲 东精精密设备(上海)有限公司市场部
Zhenzhou Lu, Marketing Planning & Information Dept, ACCRETECH (CHINA) CO., LTD



《用于缺陷评价的扫描电镜倾斜观察技术》
Development of Tilt Observation Technique for Defect Evaluation SEM "CT1000"
袁雍煜 日立高新技术(上海)国际贸易有限公司高级工程师
Yongyu Yuan, Senior Engineer, Hitachi High-Tech (Shanghai) Co., Ltd.



《从“智能检测”向“智能决策”:AI赋能检测设备的全新可能》
From “Intelligent Inspection” to “Intelligent Decision-Making”: New Possibilities for AI-Empowered Metrology and Inspection Equipment

张雪娜 深圳市埃芯半导体科技有限公司
董事长
Xuena Zhang, Chairwoman, Shenzhen Angstrom Excellence Technology Co., LTD



《化合物半导体器件全流程光学缺陷检测方案》
Full-Process Optical Defect Inspection Solution for Compound Semiconductor Devices

高昆 中电科风华信息装备股份有限公司
研发总监
Kun Gao, R&D Director, CETC Fenghua Information Equipment Co., Ltd.



《TGV全工艺栈点在线量检测解决方案》
TGV Full-Process In-line Metrology & Inspection Solution

张朝前 北京电子量检测装备有限责任公司
研发总监
ChaoQian Zhang, R&D Director, Beijing Electronics Inspection and Metrology Equipment Co., Ltd.



《量检测技术赋能先进半导体制造》
Enabling Advanced Semiconductor Manufacturing with Metrology & Inspection Technology

曾安生 御微半导体技术有限公司市场总监
Anson Zeng, Marketing Director, Yuwei Semiconductor Technology Co., Ltd



《AI及先进封装浪潮下重塑存储BI测试新范式:挑战、创新与量产突围》
Reshaping The Storage BI Testing Paradigms Amid The AI & Advanced Packaging Wave: Challenges, Innovations and Volume Production Breakouts

王建伟 上海启泰沣华半导体科技有限公司
研发副总经理
Jianwei Wang, VP of RD, Shanghai Chiptest Fenghua Semiconductor Technology Co., Ltd.

● 圆桌对话 Roundtable Discussion



圆桌对话

主持人:

季宗亮 季华资本创始人、启泰沣华创始人

嘉宾:

王 帆 上海御微半导体技术有限公司总裁

温任华 魅杰半导体设备(无锡)有限公司董事长

张 峰 江苏芯势科技有限公司董事长

张雪娜 深圳市埃芯半导体科技有限公司董事长

黄崇基 上海微崇半导体设备有限公司董事长兼总经理

Roundtable Dialogue

Moderator:

Zongliang Ji, Founder of Jihua Capital & ChiptestX

Guest:

Francis Wang, CEO, Shanghai Yuwei Semiconductor Technology Co., Ltd

Henry Wen, Chairman, Meijie Semiconductor Equipment (Wuxi) Co., Ltd.

Feng Zhang, Chairman, Jiangsu Semiinnovation Technology Co., Ltd.

Xuena Zhang, Chairwoman, Shenzhen Angstrom Excellence Technology Co., LTD

Chongji Huang, Chairman and General manager, Shanghai Aspiring Semiconductor Equipment Co., Ltd.

先进制程清洗技术及设备专题论坛

Seminar on Advanced-Process Cleaning Technology and Equipment



● 嘉宾风采 Speakers



主持人:张晓燕 盛美半导体设备(上海)股份有限公司工艺资深副总裁

Moderator: Zhang Xiaoyan, Senior Vice-President of Process Engineering, ACM Research (Shanghai), Inc.



《先进湿法清洗工艺技术挑战及发展方向》
Challenges in Advanced Wet Cleaning Process Technologies

王文军 盛美半导体设备(上海)股份有限公司工艺副总裁
Wang Wenjun, VP of Process, ACM Research (Shanghai), Inc.



《面向光电共封装应用的键合技术及演进趋势》
Bonding Technologies and Evolution Trends for Co-Packaged Optics Applications

戴风伟 华进半导体先导技术研发中心有限公司资深研发总监
Dai Fengwei, Senior R&D Director, National Center for Advanced Packaging Co., Ltd.



《先进清洗制程的挑战与ESG贡献》
Challenges and ESG Contributions of Advanced Cleaning Process Equipment

李瑞评 扬帆半导体科技(苏州)有限公司首席技术长
Jui-Ping Li, CTO, Silicar semiconductor technology (Suzhou) Co., Ltd.



《半导体装备零部件精密清洗与微污染控制》
Precision cleaning and micro contamination control of semiconductor equipment components

张正伟 安徽富乐德科技发展股份有限公司技术总监
Zhang Zhengwei, Technology Director, Ferrotec (An Hui) Technology Development Co., LTD



《先进制程用高纯PFA的制备与应用》
Preparation and Application of High-Purity PFA for Advanced Nodes

林榜佳 巨化集团有限公司可熔氟树脂产品经理
Lin Bangjia, Product Manager of Melt-Processable Fluororesin, Juhua Group Co., Ltd.

先进键合技术、制程及设备专题论坛

Seminar on Advanced Bonding Technology, Processes and Equipment



● 嘉宾风采 Speakers



Moderator: Hailan Yi, Expert PM of ZJLAB
主持人: 易海兰 张江实验室专家项目经理



《先进封装设备赋能异构集成新生态》
Advanced Packaging Equipment: Enabling
the Future of Heterogeneous Integration

余飞 北京北方华创微电子装备有限公司
POP事业单元产品与解决方案部总监
Fei Yu, Director of Unit Product and
Solution Department, Beijing NAURA
Microelectronics Equipment Co., Ltd.



《深度解析混合键合精度》
In-Depth Analysis of Hybrid Bonding Overlay

郭万里 拓荆键科(海宁)半导体设备有限公
司总经理
Wanli Guo, CEO, Piotech (Haining)
Semiconductor Equipment Co., Ltd.



《从装备到工艺: 先进键合技术赋能异质集成
规模化落地》
From Equipment to Process: Advanced
Bonding Technologies Enabling High-Vol-
ume Manufacturing of Heterogeneous
Integration

母凤文 青禾晶元半导体科技(集团)有限责
任公司创始人兼董事长
Fengwen Mu, Founder & Chairman,
iSABers Group Co., Ltd.



《Hybrid Bonding: Enabling Tomorrow's
Semiconductor Architectures》
Shuxue Tu, Sales Manager, EV Group
China Ltd.



《易卜COORS®-V硅桥先进封装技术对键合技
术的要求》
Bonding Technology Requirements for
Yibu's COORS®-V Silicon Bridge Packaging
Technology

黎明 上海易卜半导体有限公司研发副总
Ming Li, VP R&D, Shanghai Yibu
Semiconductor Co., Ltd.



《芯堆叠·键未来:先进封装中键合与解键合的核心技术突破》
Chip Stacking · Bonding the Future: Core Technological Breakthroughs in Bonding & Debonding for Advanced Packaging
王茂林 博纳半导体设备(浙江)有限公司工艺研发总监
Forest Wang, Process Development Director, Bona Semiconductor Equipment (Zhejiang) Co., Ltd



《三维集成-后摩尔时代芯片新趋势》
3D IC – New Trends of IC in the Post-Moore Era
杨列勇 物元半导体技术(青岛)有限公司联合创始人和首席科学家
Liejong Yang, Co-Founder & Chief Scientist, Wuyuan Semiconductor Technology (Qingdao) Co., Ltd.

人工智能与电子制造设备发展专题论坛

Seminar on the Development of Artificial Intelligence and Electronic Manufacturing Equipment



● 嘉宾风采 Speakers



主持人: 叶乐志 博士 中国电子专用设备工业协会副秘书长
Moderator: Ye Lezhi, Doctor, Deputy Secretary-General of China Electronic Production Equipment Industry Association



《多Agent虚拟制造赋能接近式光刻——从计算光刻到智能装备的范式变革》
Multi-Agent Virtual Manufacturing Empowering Proximity Lithography: From Computational Lithography to Intelligent Equipment

曹子峥 浙江大学长聘教授/求是特聘教授
Zizheng Cao, Tenured Professor/Qiushi Distinguished, Zhejiang University



《AI赋能半导体装备高质量发展》
AI Empowers High-quality Development of Semiconductor Equipment

巩小亮 中电科电子装备集团有限公司技术总体部主任
Xiaoliang Gong, Director of Overall Technology Department, CETC ELECTRONICS



《面向AI芯片的先进封装FOPLP与电镀技术的机遇与挑战》
Opportunities and Challenges of FOPLP and Electroplating Technologies for Advanced AI Chip Packaging

贾照伟 盛美半导体设备(上海)股份有限公司工艺资深副总裁
Zhaowei Jia, SVP of Process, ACM Research (Shanghai), Inc.



《AI-Native智能装备:重塑半导体研发与制造新范式》
AI-Native Smart Equipment: Reshaping a New Paradigm for Semiconductor R&D and Manufacturing

刘斌 埃克斯控股(北京)有限公司首席技术官,博士
Dr. Bin Liu, CTO, IKAS Holdings (Beijing) Co., Ltd.



《微环控部件与半导体整机协同机制探讨》
Discussion on the Collaborative Mechanism between Micro-Environmental Control Components and Complete Semiconductor

李小平 武汉微环控技术有限公司创始人
Xiaoping Li, Founder, Wuhan Micro-Environment Control Co., Ltd.



《集成电路产业人才需求报告及上海电机学院人才培养现状》
Research Report on Talent Demand in the Integrated Circuit Industry and the Current Status of Talent Cultivation at Shanghai Dianji University

刘娜 上海电机学院教授、产业发展研究中心集成电路产业负责人
NA LIU, Professor, Head of the Integrated Circuit Industry Division at the Industrial Development Research Center



《IBM 如何以混合云与 AI 算力解锁半导体“智造”新范式》
Unlocking the New Smart Manufacturing Paradigm in Semiconductors: IBM's Hybrid Cloud & AI Compute Approach

庞文峥 IBM 大中华区存储产品经理
Wenzheng Pang, GCG Storage Product Manager, IBM

半导体产业CEO论坛

Semiconductor Industry CEO Forum



● 嘉宾风采 Speakers



吴凯 CSEAC组委会执行副秘书长
Kevin Wu, Executive Deputy Secretary-General of the CSEAC Organizing Committee



吴炜无锡高新区党工委委员、新吴区委常委、副区长、梅村街道党工委书记
Wu Wei, Member of the Party Working Committee of Wuxi National Hi-Tech District (WND), Member of the Standing Committee of the CPC Xinwu District Committee, Vice Mayor of Xinwu District, and Secretary of the Party Working Committee of Meicun Sub-district



《迈向全球增长新格局：算力重塑下的芯片、主权与全球贸易》
Entering a new global growth regime: Chips, sovereignty, and trade
卢姿蕙 牛津经济研究院 亚太首席经济学家
Louise Loo, Head of Asia Economics, Oxford Economics



《AI 新周期：硅片产业机遇与西安奕材产业担当》
New AI Cycle: Silicon Wafer Industry Opportunities and Xi'an ESWIN Materials' Industrial Responsibility
杨新元 西安奕斯伟材料科技股份有限公司董事长
Yang Xinyuan, Chairman of Xi'an ESWIN Materials Technology Co., Ltd.



《先进技术和高生产力双轮驱动半导体工艺设备发展》
Dual-wheel Drive of Advanced Technology and High Productivity Promotes the Development of Semiconductor Process Equipment
刘二壮 普达特科技有限公司董事长/CEO
Liu ErZhuang, Chairman/CEO of Productive Technologies Company Limited



《中国设备产业本土化的2.0版发展目标》
The development goal of the 2.0 version of China's equipment industry localization
陈捷 盛红晔半导体董事长
Jay Jie Chen, Chairman of Britech Semiconductor

● 圆桌讨论 I : 如何实现合作共赢, 打造健康的供应链体系

Panel Discussion I : How to Achieve Win-Win Cooperation and Build a Healthy Supply Chain



圆桌对话

主持人:

沈翊 泓明供应链集团董事长

嘉宾:

何小龙 华润微电子有限公司董事长

邱慈云 上海硅产业集团股份有限公司总裁

陈吉 北京北方华创微电子装备有限公司总裁

刘二壮 普达特科技有限公司董事长/CEO

陈捷 盛红半导体董事长

Roundtable Dialogue

Moderator:

Sysy Shen, Chairman of HMG Supply Chain Group

Guest:

He Xiaolong, Chairman of China Resources Microelectronics Limited

Chiu,Tzu-Yin, President of National Silicon Industry Group

Chen Ji, President of Beijing NAURA Microelectronics Equipment Co., Ltd.

Liu ErZhuang, Chairman/CEO of Productive Technologies Company Limited

Jay Jie Chen, Chairman of Britech Semiconductor

● 嘉宾风采 Speakers



《AI——半导体产业的发动机》

AI - Motor of the Semiconductor Industry

奥泰因·赫尔佐格 中国工程院外籍院士、德国国家工程院院士、同济大学教授
Otto Heinrich Herzog, Foreign Member of the Chinese Academy of Engineering; Member of the National Academy of Science and Engineering (Acatech, Germany); Professor at Tongji University



《俄中半导体设备制造领域: 学术科研、工业界与高校的战略伙伴关系》

The Russian Academy of Sciences: many years of experience in solving industrial challenges. Now — in microelectronics

戈尔巴采维奇·亚历山大 科学院正式成员
Aleksandr Gorbatshevich, Full Member of RAS



《晶圆制造设备的趋势分析: 人工智能、制造复杂度与中国的崛起》

The Future of Wafer Fab Equipment: AI, Manufacturing Complexity, and China's Rise

Gary Huang Yole集团公司副总裁、亚太区研究与业务开发负责人
Gary Huang, Corp VP, Head of Asia Pacific, Research and Business Development at Yole Group



《协作融合构建高韧性的半导体产业链》
Collaborative Integration to Build a Highly Resilient Semiconductor Industry Chain

徐晏清 霍尼韦尔工业测量与控制大中华区总经理
Rebecca Xu, General Manager Greater China of Honeywell Industrial Measurement & Control



《RISC-V构建未来开放的计算生态》
RISC-V is shaping the future open computing ecosystem

彭剑英 芯来智融半导体科技(上海)股份有限公司总裁
Peng Jianying, President of Nuclei System Technology Co., Ltd.



《基于系统工程的深紫外光刻物镜设计与制造关键技术》
Key Technologies for Design and Manufacturing of Deep Ultraviolet Lithography Objective Lens Based on Systems Engineering

高安 上海米莱芯程半导体有限公司CEO
Gao An, CEO of Shanghai MILEX Semiconductor Co., Ltd.



《AI芯片先进封装发展与测试技术研究》
Research on Development and Testing Technology of Advanced Packaging for AI Chips

钟锋浩 杭州长川科技股份有限公司董事、副总经理
Zhong Fenghao, Director and Deputy General Manager of Hangzhou Changchuan Technology Co., Ltd.



《关键尺寸量测装备国产化:CD-SEM引领产业协同创新》
Advancing Domestic Critical Dimension Metrology Equipment: How CD-SEM Drives Collaborative Innovation Across the Semiconductor Value Chain

王志刚 惠然微电子技术(无锡)有限公司董事长
Zeno Wang, Chairman of Wellrun Microelectronics Technology Co., Ltd.



《从芯片到智能系统:质量管理的下一次跃迁》
From Chips to Intelligent Systems: The Next Leap in Quality Management

陈宇晓 亚旗集团CEO
David Chen, CEO of ACCU Group



《全球专利地图视角下的半导体产业发展趋势》
Trends in the Development of the Semiconductor Industry from a Global Patent Map Perspective

康纳蔚 美国亚司特博钦律师事务所合伙人
Mr. Kyle R. Canavera, Partner of Ashurst Perkins Coie



Morocco Now

Meryem KABBADJ, 摩洛哥投资与出口发展局 (AMDIE) 航空航天与电子部主管
Meryem KABBADJ, Head of Aerospace & Electronics Department of Moroccan Investment and Export Development Agency — AMDIE



《日本及全球半导体产业与制造设备中期需求预测》

Medium-term Demand Forecast for the Semiconductor Industry and Manufacturing Equipment in Japan and Worldwide

Tommy Sato 日本半导体设备协会副秘书长
Tommy Sato, Deputy Secretary General of Semiconductor Equipment Association of Japan

● 圆桌讨论 II : 如何实现全球产业协作融合

Panel Discussion II: How to Achieve Global Industrial Collaboration and Integration



圆桌对话

主持人:

于治 中合联创(大连)资产管理有限公司创始合伙人

嘉宾:

Roger Costa 加泰罗尼亚半导体联盟负责人

张哲伟 爱尔兰投资发展局中国区总监

Tadhg O' Callaghan 爱尔兰贸易与科技局大中国区负责人

杜晶 阿联酋迪拜国际自由区管理局中国区商务代表

李可道 马波斯(上海)测量设备科技有限公司大中华区总裁

马清海 SMC自动化有限公司总经理

王志刚 惠然微电子技术(无锡)有限公司董事长

李昌哲 意创科技有限公司执行董事, 航菱微(泰州)科技有限公司常务副总

Roundtable Dialogue

Moderator:

Nick Yu, Founding Partner of Zhonghe Lianchuang (Dalian) Asset Management Co., Ltd.

Guest:

Roger Costa, Head of Catalonia Semiconductor Alliance

Jervy Zhang, Director China of IDA Ireland

Tadhg O' Callaghan, Director of Enterprise Ireland for Greater China

Robin Du, China Business Representative of International Free Zone Authority(IFZA)

Riccardo Budries, CEO of Marposs (Shanghai) Technologies Co., Ltd.

Ma Qinghai, General Manager of SMC Automation China Co., Ltd.

Zeno Wang, Chairman of Wellrun Microelectronics Technology Co., Ltd.

CJ Li, Executive Director of Exacta Integrated Engineering SDN BHD/
Executive Vice President of Hanglingwei (Taizhou) Technology Co., Ltd.

迈向自主可控的半导体制造之路

Path to Sovereign Semiconductor Manufacturing



● 嘉宾风采 Speakers



主持人: Aleksander Lvov 博士
“ISTC MIET” 股份有限公司首席执行官
Moderator: Dr. Aleksander Lvov
CEO, Joint-Stock Company "International Science and Technology Center MIET"



《迈向自主可控的半导体制造之路》
Path to Sovereign Semiconductor Manufacturing
Anton Kostikov, 工业发展中心电子战略
研究主任
Anton Kostikov, Director of Strategic
Research Electronics, Industrial
Development Center



《为俄罗斯电子工业提供化学品和先进材料
的综合方法: 从研发到生产》
An Integrated Approach to Supplying
Russia's Electronics Industry with
Chemicals and Advanced Materials:
From Research to Production
Uliana Stepanova, 工业发展中心电子工
业化学品部负责人
Uliana Stepanova, Head of the Electron-
ics Industry Chemicals Division,
Industrial Development Center



《一系列俄罗斯用于半导体材料生长和加
工的设备和技术的展示》
Presentation of a series of Russian
equipment and technologies for
growing and processing semiconductor
materials

Andreev Dmitry, “LASSARD” 有限责任公
司商务总监
Andreev Dmitry, Commercial Director,
Limited Liability Company «LASSARD»



《俄罗斯光学投影、光刻及电子束光刻设备
产品组合推介》
Presentation of the Russian equipment
portfolio for optical projection,
lithography, electron-beam lithography

Kovalev Anatoly, 泽列诺格勒纳米技术中
心股份公司首席执行官
Kovalev Anatoly, CEO, JSC Zelenograd
Nanotechnology Center



《用于蚀刻和薄膜沉积的簇状系统》
Cluster-type systems for etching and
thin-film deposition

Yeritsyan Georgy, 精密机械制造研究所研
发部主任
Yeritsyan Georgy, Head of the R&D
Department Research Institute for
Precision Machine Manufacturing



《俄罗斯用于微波电子和光子学的外延和晶圆加工设备》
Russian epitaxial and wafer processing equipment for microwave electronics and photonics

Alexeev Alexey 博士, «Semiconductor Technologies and Equipment» 股份有限公司首席执行官
Alexeev Alexey, PhD, CEO, Joint Stock Company «Semiconductor Technologies and Equipment»



《俄罗斯用于直接无掩模制造电子和光电子器件的增材制造设备》
Russian additive equipment for direct maskless fabrication of electronic and optoelectronic devices

Efimov Aleksei, 莫斯科物理技术学院总设计工程师
Efimov Aleksei, Chief Design Engineer, Moscow Institute of Physics and Technology



《适用于最大200毫米半导体和蓝宝石晶圆的引入缺陷检测系统, 支持从开放式托盘和SMIF托盘进行手动和自动装卸》
Introduced-defect inspection system for semiconductor and sapphire wafers up to 200 mm, with manual and automated loading/unloading from open cassettes and SMIF pods

Vorobev Ivan, GNTECH 有限责任公司 ‘商务总监
Vorobev Ivan, Commercial Director, GNTECH LLC



《用于180–90nm技术工艺的光刻胶和浆料》
Photoresists and slurries for 180–90 nm technology processes

Varlamov Denis, 分子电子研究所特殊材料部主任
Varlamov Denis, Head of Special Materials Department Molecular Electronics Research Institute



《将先进的多级SRAF优化技术集成到基于传送带的ILT工作流程中, 用于光掩模层设计》
Toward Integrating Advanced Multilevel SRAF Optimization Techniques into Conveyor-Based ILT Workflow for Photomask Layer Design

Fedorov Igor 博士, 俄罗斯储蓄银行执行董事
Fedorov Igor, PhD, Executive Director, Sberbank of Russia

新器件新工艺推动新材料新设备创新发展论坛

Forum on New Devices and Processes Driving Innovation and Development of New Materials and Equipment



● 嘉宾风采 Speakers



陶建中 江苏省半导体行业协会秘书长
Jianzhong Tao, Secretary-General of
Jiangsu Semiconductor Industry
Association



《集成电路材料创新联合体IC观察》
IC Watch from ICMIC
主持人:冯黎 集成电路材料创新联合体秘
书长、上海硅产业集团总裁助理
Moderator: Flora Feng, Secretary-Gen-
eral of ICMIC & Assistant to the
President of National Silicon Industry
Group



《聚焦光学硅,打通量产路:光子芯片产业
化探索与实践》
LNOI to Mass Production: Exploration
and Practice in Photonic Chip Industri-
alization
李军 上海交大无锡光子芯片研究院/光子
芯谷创新中心总经理
Jun Li, General Manager, Chip Hub for
Integrated Photonics Xplore (CHIPX)



《AI浪潮重塑薄膜沉积设备新机遇》
Angstrom Metallization: The Hidden
Backbone of AI Infrastructure

韦玮 研微(江苏)半导体科技有限公司
商务总监
Woody Wei, Business Development
Director, Pioneer Semiconductor
Research



《AI赋能IC材料研发与产业化进程》
AI-Empowered R&D and Industrializa-
tion of IC Materials
林明献 上海硅产业集团股份有限公司技术
应用工程中心总经理
Ming-Hsien Lin, General Manager of
Application Technology Engineering
Center, National Silicon Industry Group



《先进工艺制程下过程诊断子系统的需求
演进与技术趋势》
Demand Evolution & Technology Trends
for Process Diagnostics in Advanced Nodes
陈传喜 上海车仪田科技有限公司副总经理
Andy Chen, Deputy General Manager,
Shanghai Cheyitian Technology Co.,Ltd.



《集成电路材料检测技术新进展》 New Developments in IC Materials Metrology and Inspection

李春华 上海集成电路材料研究院有限公司
检测分析事业部主任
Chunhua li, Lab Director, Shanghai
Integrated Circuit Materials Research
Institute Co., Ltd.

● 圆桌讨论 Round-table Discussion



圆桌对话

主持人:

花菓 求是缘半导体联盟常务副秘书长, 正海资本合伙人

嘉宾:

周逸晟 集成电路材料创新联合体副秘书长、上海集成电路材料
研究院创新联合部部长

唐韩卿 东华大学集成电路校友会秘书长

李军 上海交大无锡光子芯片研究院/光子芯谷创新中心总经理

夏前明 夏罗登工业科技(上海)股份有限公司总经理

陈传喜 上海车仪田科技有限公司副总经理

韦玮 研微(江苏)半导体科技有限公司商务总监

Roundtable Dialogue

Moderator:

Winston Hua, Executive Deputy Secretary-General, Truth Semi Group &
Partner at Royalsea Capital

Guest:

Yicheng Zhou, Vice Secretary-General of ICMIC & Director of the Joint
Innovation Department at Shanghai Institute of IC Materials

Hanqing Tang, Secretary-General of Donghua University Integrated Circuit
Industry Alumni Association

Jun Li, General Manager, Chip Hub for Integrated Photonics Xplore (CHIPX)

Tony, General Manager, Schalod Industry Technology (Shanghai) Co.,Ltd

Andy Chen, Deputy General Manager, Shanghai Cheyitian Technology Ltd.

Woody Wei, Business Development Director, Pioneer Semiconductor
Research

半导体设备平台化与核心部件协同论坛（上）

Forum on the Platformization of Semiconductor Equipment and Synergy among Core Parts (Part I)



● 嘉宾风采 Speakers



主持人:李昌哲 意创科技有限公司执行董事、航菱微(泰州)科技有限公司常务副总
CJ Li, Executive Director of Exacta Integrated Engineering SDN BHD/
Executive Vice President of Hanglingwei (Taizhou) Technology Co., Ltd.



《全链数据体系提升跨境供应链韧性》——重点阐述以数据标准化为底座、以“三账五流”框架为基础、以人工智能为引擎的“全链数据体系”构建路径
《Building Cross-Border Supply Chain Resilience Through a Full-Chain Data System》— Focusing on how to build a “full-chain data system” with data standardization as the foundation, the Three-Ledger Accounting and Five-Flow Consistency framework as the core structure, and artificial intelligence as the driving engine.

洪世畅 上海泓明供应链集团产品总监
David, Product Director, HMG Supply Chain Group



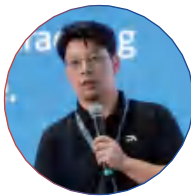
《AI+数字孪生驱动AMHS智能化跃迁》
AI + Digital Twin: Powering AMHS' s Intelligent Leap

杨海军 合肥欣奕华智能机器股份有限公司副总裁
Yang Haijun , Vice President, Hefei Sineva Intelligent Machine Co., Ltd.



《埃米时代的量测革命:CD-SEM技术演进、产业趋势与国产电子束装备突围》
Metrology Revolution in the Angstrom Era: CD-SEM Evolution, Industry Trends, and the Path Toward Breakthroughs in Domestic Electron Beam Equipment

王志刚 惠然微电子技术(无锡)有限公司董事长
Zeno Wang , Chairman ,Wellrun Microelectronics Technology Co., Ltd.



《微波等离子体—含氟废气(PFCS)高效处理技术》
Microwave Plasma – High-efficiency Treatment Technology for Fluorine-containing Exhaust Gas (PFCS)

周益斌 致和半导体设备(江苏)有限公司首席技术官
Zhou Yibin, CTO, Firsquare Semiconductor Equipment (Jiangsu) Co., Ltd.



《半导体设备核心电源技术发展的探索与实践》
Exploration and Practice of Core Power Supply Technology Development for Semiconductor Equipment

尹向阳 广州金升阳科技有限公司董事长
George, Chairman, MORN SUN Guangzhou Science & Technology Co.,Ltd.



《新施诺50Kg重载PLP OHT:破局先进封装物流瓶颈,赋能AI算力规模化释放》
Xinshino's 50kg-Class PLP-Dedicated OHT: Breaking the Advanced Packaging Logistics Bottleneck to Enable AI Computing Power at Scale

路通 苏州新施诺半导体设备股份有限公司技术副总经理
Lu Tong, Deputy General Manager of Technology, Suzhou Xinshinuo Semiconductor Equipment Co., Ltd.



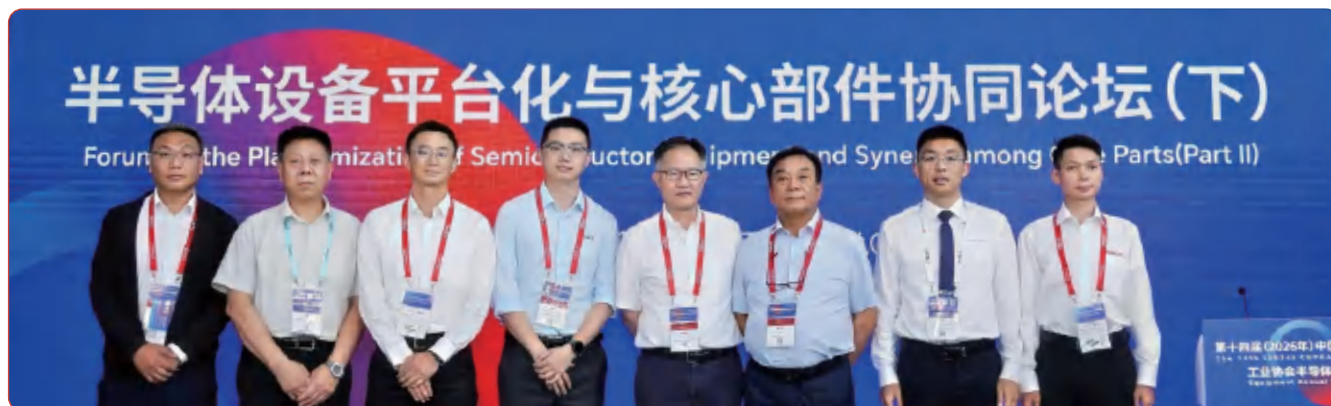
《先进封装关键装备及核心技术突破》
Key Equipment and Core Technology Breakthroughs in Advanced Packaging
喻杰 迈为技术(珠海)有限公司副总经理兼总经理特助
Yu Jie, Deputy GM & Exec. Asst. to GM, Maxwell Technologies (Zhuhai) Co., Ltd.



《晶圆键合及国产设备的挑战和突破》
Wafer Bonding: Challenges and Breakthroughs in Domestic Equipment
曲鲁杰 深圳市克洛诺斯科技有限公司高级技术顾问
Qu Lujie, Senior Technical Advisor, Shenzhen Cronus Technology Co., Ltd.

半导体设备平台化与核心部件协同论坛（下）

Forum on the Platformization of Semiconductor Equipment and Synergy among Core Parts (Part II)



● 嘉宾风采 Speakers



主持人:裴大章 中国电子专用设备工业协会监事
Moderator: Pei Dazhang, Supervisor, China Electronic Production Equipment Industry Association



《世界最大微振动模拟振动台的性能与应用》
Performance and Applications of the World's Largest Micro-vibration Shaking Table
冯德民 中国电子工程设计院股份有限公司日本工程院院士, 国投集团首席专家
HYOU TOKUMIN, Member, The Engineering Academy of Japan & Chief Expert at SDIC Group, China Electronics Engineering Design Institute CO., LTD.



《国产量检测精密运动台:不止替代,更敢领跑》
Domestic Precision Motion Stages for Metrology & Inspection: Beyond Replacement, Leading the Race
赵磊 江苏集萃苏科思科技有限公司量检测与光刻事业部总经理
Zhao Lei, Jiangsu JITRI SKS Technologies Co., Ltd.



《制程之困, 光束为解: 半导体精密制造的激光新路径》
Breaking Process Barriers with Laser:
New Frontiers in Semiconductor

刘超 优耐特高精(上海)机床有限公司
产品经理
Liu Chao, Production Manager of
CHARMILLES, United Machining



《工艺驱动·厂机协同 —— 半导体设备与洁净厂房一体化设计之路》
Process-Driven, Fab & Equipment Synergy
— The Integrated Design Path of Semiconductor Equipment and Cleanroom Facilities

占鹏飞 中国电子系统工程第二建设有限公司
电子行业中心副主任
Zhan Pengfei, Deputy Director Electronics
Industry Center, China Electronics System
Engineering No.2 Construction Co., Ltd.



《从半导体温控设备看当前的课题与今后的方向》
Looking at current issues and future
directions from the perspective of semicon-
ductor temperature control equipment

王雨 鸿世佰熠半导体设备(上海)有限公司
联合创始人
Wang Yu, Co-founder, Hongshibaiyi
Semiconductor Equipment (Shanghai)
Co., Ltd.



《聚焦核心零部件 助力半导体行业发展》
AURASKY core components support the
development of the semiconductor
industry

王弘 北京华丞电子股份有限公司解决方案
营销中心总监
Wang Hong, Director of Solution
Marketing Center, Beijing AURASKY
Electronics Co., Ltd.



《大尺寸SiC减薄解决方案》
Large-format SiC Grinding Solutions

梁津 北京中电科电子装备有限公司
产品研发部部长
Jessie Liang, Products R&D Depart-
ment Minister, CETC BEIJING
ELECTRONIC EQUIPMENT CO.LTD



《发那科智能制造驱动半导体产业降本、提质、增效》
Fanuc Intelligent Manufacturing Drives
Cost Reduction, Quality Improvement,
and Efficiency Enhancement in the
Semiconductor Industry

徐运华 上海发那科智能机械有限公司
销售经理
Xu Yunhua, Sales Manager, SHANG-
HAI-FANUC Robomachine Co., Ltd.

新产品、新技术发布会 New Product and Technology Launch



● 嘉宾风采 Speakers



主持人：陈柯 CSEAC组委会
Moderator: Chen Ke CSEAC Organizing Committee



《集成电路制造的“嗅觉神经”——残余气体分析仪》
The "sensory nerve" for integrated circuit manufacturing - residual gas analyzer
成功 上海航天裕达科技有限公司市场部副经理
Cheng Gong, Marketing Deputy Manager, Shanghai Aerospace Yuda Technology Co., Ltd.



《等离子体诊断多通道零像散高分辨光谱仪》
High-resolution Multi-channel Astigmatism-free Spectrometer for Plasma Diagnostics
胡松婷 上海复享光学股份有限公司仪器事业部产品总监
Songting Hu, PM, ideaoptics Inc.



《合肥欣奕华高性能贴片与键合设备助力先进封装国产化进程》
High-Performance Die Attach and Bonding Equipment from Hefei Sineva: Driving the Localization of Advanced Packaging
何峰光 合肥欣奕华智能机器股份有限公司中央研究院院长
Fengguang He, Dean of Central Research Institute, Hefei Sineva Intelligent Machine Co., Ltd.



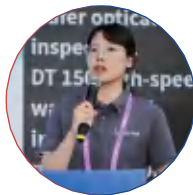
《化圆为方！容道社破解大尺寸FOPLP封装“卡脖子”难题，加速Chiplet与AI算力落地》
Squaring the Circle! RDS Breaks Bottlenecks in Large-Size FOPLP Packaging to Accelerate the Implementation of Chiplet and AI Computing Power
廖展展 销售总监 江苏容道社半导体设备科技有限公司
Zhanzhan Liao, Sales Director, Jiangsu RDS Technology Co., Ltd.



《激光干涉仪在半导体行业中的应用》
Application of Laser Interferometers in the Semiconductor Industry
夏如孝 北京镭测科技有限公司副总经理
Ruxiao Xia, Deputy General Manager, Beijing Leice Technology Co., Ltd.



《基于系统工程方法的光刻曝光系统的核心部件》
Core Components of Lithography Exposure System Based on Systems Engineering Methodology
郭银章 (米莱芯程) 资深光学技术专家, (芯颐和) CTO
Yinzhang Guo, Senior Optical Technology Expert, CTO of Shanghai Neoeho Technology Co., Ltd.



《高速晶圆螺旋检测运动平台：实现晶圆光学检测效率与精度再提升》
High-Speed Wafer Spiral Inspection Motion Platform – Elevating Optical Inspection Efficiency & Precision
沈维韬 无锡地心科技有限公司市场部负责人
Vita, Head of Marketing, WUXI Coretech Technology Co., Ltd.



《多模态AI检测技术助力半导体先进制造良率提升》
Multi-modal AI Inspection Technology Enables Yield Improvement in Advanced Semiconductor Manufacturing
冯昆仑 镁伽科技高级产品经理
Coolun Feng, Senior Product Manager at MegaRobo Technologies

风米人力行：高校产学研成果路演

Human Resources: Thematic Roadshow on the Commercialization of University-Industry-Research Collaboration



● 嘉宾风采 Speakers



主持人：柴俊宇教授 杭州电子科技大学
Moderator: Chai Junyu, Professor,
Hangzhou Dianzi University



主办方开场白 戴雪梅 CSEAC组委会, 风米
网人力行校企对接负责人
Host's opening remarks: Dai Xuemei,
CSEAC Organizing Committee, responsi-
ble person for the connection between
Fengm.cn and human resources, schools,
and enterprises



陈涛 工业和信息化部教育与考试中心高级
工程师
Chen Tao, Senior Engineer, Education and
Examination Center of the Ministry of
Industry and Information Technology



《微机电能源 (MEME) 热电芯片》
Micro-Electromechanical Energy
(MEME) Thermoelectric Chip

胡志宇教授 上海交通大学张江高等研究院
Hu Zhiyu, Professor, Zhangjiang
Institute for Advanced Study, Shanghai
Jiao Tong University



《面向先进制程的ALD精准功能薄膜材料及
核心工艺》
Precision Functional Thin Films and
Core ALD Processes for Advanced Nodes

徐甲强教授 上海大学理学院
Xu Jiaqiang, Professor, College of
Sciences, Shanghai University



《新型存储器技术与芯片安全设计》
Novel Memory Technology and Chip
Security Design

刘泰琦 山东大学信息科学与工程学院
Liu Taiqi, School of Information Science
and Engineering, Shandong University



《超高孔隙率实心骨架泡沫铜及其三明治结构材料》
Ultra-High Porosity Solid-Skeleton Copper Foam and Its Sandwich Structure Material

肖健博士 江西理工大学材料学院
Xiao Jian, Dr., School of Materials Science and Engineering, Jiangxi University of Science and Technology



《碳化硅衬底激光改质剥离技术研究》
Research on Laser Modification and Lift-off Technology of SiC Substrates

陆喜文助理研究员 中国科学院宁波材料技术与工程研究所
Lu Xiwen, Assistant Researcher, Ningbo Institute of Materials Technology and Engineering, Chinese Academy of Sciences



《AI 驱动的先进制程半导体设备和工艺开发》
AI-Driven Development of Advanced Nodes Semiconductor Equipment and Processes

马奕涛教授 浙江大学集成电路学院
Ma Yitao, Professor, College of Integrated Circuits, Zhejiang University



《硬科技成果转化视角下:技术转移复合型人才的培养路径与实践》
From the Perspective of Hard-Tech Commercialization: Cultivation Pathways and Practices for Interdisciplinary Talent in Technology Transfer

侯家佳 复旦大学技术转移硕士项目主任
Hou Jiajia, Program Director, MTT Program, Fudan University



主持人:唐燕群教授 中山大学
Moderator: Tang Yanqun, Professor, Sun Yat-sen University



《半导体工艺优化大模型》
Large Model for Semiconductor Process Optimization

熊红凯教授 华东师范大学信息与电子工程学院
Xiong Hongkai, Professor, School of Information and Electronic Engineering, East China Normal University



《太赫兹半导体无损检测》
Terahertz Semiconductor Non-destructive Testing

胡旻教授 电子科技大学电子科学与工程学院
Hu Min, Professor, School of Electronic Science and Engineering, University of Electronic Science and Technology of China



《金刚石 MPCVD 生长和电子器件应用》
MPCVD Growth of Diamond and Its Applications in Electronic Devices

陈军飞博士 西安电子科技大学微电子学院
Chen Junfei, Dr., School of Microelectronics, Xidian University



《先进气体流量测控技术研究》
Advanced Mass Flow Sensor technologies

林玉哲博士 山东大学信息科学与工程学院
Lin Yuzhe, Dr., School of Information Science and Engineering, Shandong University



《实时反馈原子级半导体TCAD》
Atomic-Level Semiconductor TCAD with
Real-Time Feedback

陈竞哲教授 上海大学理学院
Chen Jingzhe, Professor, School of
Sciences, Shanghai University



《AI+GPU构架+下一代CAE软件》
AI + GPU Architecture and Next-Genera-
tion CAE Software

王子啸 重庆理工大学车辆工程学院
Wang Zixiao, School of Vehicle Engineer-
ing, Chongqing University of Technology



《半导体先进封装测试设备及核心部件产
业化》

Industrialization of Advanced Packaging
& Test Equipment and Core Compo-
nents for Semiconductors

叶乐志 北京工业大学教授
Ye Lezhi, Professor, Beijing University of
Technology



《高精度电-热协同表征平台 (ET-1000)》
High-Precision Electro-Thermal Co-Char-
acterization Platform (ET-1000)

李骏康教授 浙江大学集成电路学院
Li Junkang, Professor, College of
Integrated Circuits, Zhejiang University



《双偏振-双域融合光纤模式分解与偏振态智
能测量系统》
Dual-Polarization and Dual-Domain Fusion
Fiber Mode Decomposition and Intelligent
Polarization State Measurement System

柴俊宇教授 杭州电子科技大学理学院
Chai Junyu, Professor, School of Sciences,
Hangzhou Dianzi University

风米人力行：企业人才需求发布会

Human Resources: Thematic Conference on Corporate Talent Demand Release



● 嘉宾风采
Speakers



主办方开场白 戴雪梅 CSEAC组委会, 风米网人力行校企对接负责人
Host's opening remarks: Dai Xuemei, CSEAC Organizing Committee, responsible person for the connection between Fengm.cn and human resources, schools, and enterprises



《中微公司2027企业人才需求发布》
2027 Corporate Talent Demand Announcement of AMEC
主持人: 杨俊 集团副总裁, 人力资源, 中微半导体设备(上海)股份有限公司
Moderator: Yang Jun, Group Vice President, Human Resources, Advanced Micro-Fabrication Equipment Inc. China



《北方华创2027校招宣讲》
2027 Campus Recruitment Presentation of NAURA
王铮 高校关系总监, 北京北方华创微电子装备有限公司
Wang Zheng, Director, Beijing NAURA Microelectronics Equipment Co., Ltd.



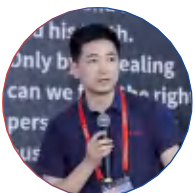
《拓荆科技文化传承与人才发展理念》
Piotech: Cultural Heritage and Talent Development Philosophy
马俊 人力资源部总监, 拓荆科技股份有限公司
Ma Jun, Director, Piotech, Inc



《掌控温度, 定义精度——与奥德一起, 做半导体温控制造的“隐形冠军”》
Master temperature, define precision — with Aode, be the hidden champion in semiconductor temperature control manufacturing
咸伟 高级人事主管 苏州奥德高端装备股份有限公司
Xian Wei, HR Manager, Suzhou AODE Precise Equipment Co., Ltd.



《康姆艾德公司介绍和人才发展》
Comet Company Introduction and Talent Development
王灿灿 销售 康姆艾德机械(上海)有限公司
Wang Vanessa, Sales, COMET



《康姆艾德公司介绍和人才发展》
Comet Company Introduction and Talent Development
孙伟 招聘 康姆艾德机械(上海)有限公司
Sun Dean, HR, COMET



《破局与突围: 半导体设备企业人才战略的升级之路》
Talent Strategy 2.0: Breaking Through for Semiconductor Equipment Players
绳欣航 招聘主管 北京电子量检测装备有限责任公司
Sheng Winnie, HR Manager, Beijing Electronics Inspection and Metrology Equipment Co., Ltd.



《精密制造, 最缺人: 佰控的人才观与行业机会》
"Precision Manufacturing Faces Its Biggest Talent Crunch: BICCNS Talent Philosophy and Industry Opportunities"
丁杨 人事经理 苏州佰控传感技术有限公司
Ding Yang, HR Manager, Suzhou Baicon Sensor Technology Co., Ltd.



《“恒”等你来, 遇见不一样的自己》
Join CSL, Discover a Better Version of Yourself
郭东霞 HRD 深圳市恒运昌真空技术股份有限公司
Guo Rachel, HRD, Shenzhen CSL Vacuum Science And Technology Co., Ltd.

西电集成电路行业校友太湖论坛

Xidian University Integrated Circuit Industry Alumni Taihu Forum



● 嘉宾风采 Speakers



主持人:孙斌 西电上海校友会执行副会长
Moderator: Sun Bin, Executive Vice President, Shanghai Alumni Association of Xidian University



王志越 中国电子专用设备工业协会秘书长
Wang Zhiyue, Secretary-General, China Electronic Production Equipment Industry Association



张玉明 西电微电子行业校友会理事长
Zhang Yuming, Chairman, Microelectronics Alumni Association of Xidian University



韩懋杰 校友事务与对外合作处校友事务办公室副主任
Han Maojie, Deputy-Director, Alumni Affairs Office, Office of Alumni Affairs and External Cooperation



张永刚 西安电子科技大学无锡校友会常务副会长兼秘书长
Zhang Yonggang, Executive Vice-President and Secretary-General, Xidian University Wuxi Alumni Association



《西电集成电路学部介绍、科技成果展示》
About the Faculty of Integrated Circuits, Xidian University & Showcase of Scientific and Technological Achievements
肖刚 西安电子科技大学集成电路学部党委书记
Xiao Gang, Party Secretary, Faculty of Integrated Circuits, Xidian University



《西电集成电路学部十大校企合作项目发布》
Release of Ten University-Enterprise
Cooperation Projects, Faculty of
Integrated Circuits, Xidian University

肖刚 西安电子科技大学集成电路学部党委书记
Xiao Gang, Party Secretary, Faculty of
Integrated Circuits, Xidian University



《面向下一代智算集群网络 CPO 硅光互连
解决方案》

Solution of CPO-Silicon-Photonics
Interconnection for Next-Generation
Intelligent Computing Cluster Networks
丁同浩博士 格创通信(浙江)有限公司副总裁
Ding Tonghao, Dr., Vice President,
GrandTrans (Zhejiang) Co., Ltd.



《后摩尔时代:华为韬定律与中国半导体投资
机遇》

Post-Moore Era: Huawei's Tao Law and
Investment Opportunities in China's
Semiconductor Industry
谢建友 齐力半导体(绍兴)有限公司董事长
Xie Jianyou, Chairman, Qili Semiconductor
(Shaoxing) Co., Ltd.



《AI驱动下的硅光集成工艺发展介绍》
AI-Driven Development of Silicon
Photonics Integration Processes

胡鑫 联合微电子中心有限责任公司
市场负责人
Hu Xin, Marketing Lead, United
Microelectronics Center Co., Ltd.



《蓝宝石基GaN的优异特性以及器件在
AIDC和新能源领域的应用》
Excellent Properties of Sapphire-Based
GaN and Device Applications in AIDC
and New Energy Fields

张安乐 上海格晶半导体有限公司产品总监
Zhang Anle, Director of Product, Shanghai
Gejing Semiconductor Co., Ltd.



《超宽禁带氧化镓半导体外延材料与器件》
Ultra-Wide Bandgap Gallium Oxide
Semiconductor Epitaxial Materials and
Devices

彭博 镓创未来半导体科技(晋江)有限公司
董事长
Peng Bo, Chairman, Gallium Future
Semiconductor Technology (Jinjiang)
Co., Ltd.



《金刚石MPCVD生长和电子器件应用》
MPCVD Growth of Diamond and Its
Applications in Electronic Devices

任泽阳 西安电子科技大学微电子学院教授
Ren Zeyang, Professor, School of
Microelectronics, Xidian University



《砺铸智能:用"芯"创造美好生活》
LIZHU INTELLIGENT: Create a Better Life
with Chips

唐亮 砺铸智能设备有限公司董事长/总经理
Tang Liang, Chairman & General
Manager, Lizhu Intelligent Equipment
Co., Ltd.

2026集成电路材料设备零部件协同发展论坛 暨06专项“集成电路关键原辅材料”项目与标准宣贯

2026 Integrated Circuit Materials, Equipment & Components Collaborative Development Forum
— Special Project 06 IC Key Raw & Auxiliary Materials Project & Standards Dissemination



● 嘉宾风采 Speakers



主持人:石瑛 集成电路材料产业技术创新
联盟秘书长
Moderator: Ingrid Shi, Secretary General
of ICMtia



《半导体零部件用CVD装备技术及应用》
Technology and Application of CVD
Equipment for Semiconductor Components

田冬龙 山西中电科电子装备有限公司副
总经理兼涂层事业部部长/技术总监/高级
工程师
Donglong Tian, Deputy General
Manager, Minister & Technical Director
of Coating, Shanxi CETC Electronic
Equipment Co., Ltd.



《半导体芯片制造用CMP精密抛光头零部
件的国产化及组装技术服务》
Localization and Assembly Technical
Services for CMP Precision Polishing
Head Components for Semiconductor
Chip Manufacturing

左威 上海润平电子材料有限公司副总经理
Wei Zuo, Deputy General Manager,
Shanghai RunPin Electronic Materials
Co., Ltd.



《先进陶瓷材料和核心零部件在半导体装
备中的应用》
Application of Advanced Ceramic
Materials and Core Components in
Semiconductor Equipment

刘先兵 苏州珂玛材料科技股份有限公司
董事长兼总经理
Xianbing Liu, Chairman & General
Manager, Suzhou Kema Materials
Technology Co., Ltd.



《半导体设备用石墨零部件国产化进展》
Progress in the Localization of Graphite
Components for Semiconductor
Equipment

周明 赛迈科先进材料股份有限公司总经理
Ming Zhou, General Manager, SIAMC
Advanced Materials Co., Ltd.,



《全球半导体设备与气流场零部件发展新
趋势》
Emerging Trends in Global Semiconduc-
tor Equipment and Gas Flow Field
Components

杨绍辉 星奇(上海)半导体有限公司副总经理
Shaohui Yang, Deputy General Manager
, Xingqi (Shanghai) Semiconductor Co.,
Ltd.



《集成电路用氟聚合物研发与应用进展》
Advances in Research and Application of
Fluoropolymers for Integrated Circuits
at Nanjing University; Academician, the
Chinese Academy of Sciences

孟庆文 浙江巨化股份有限公司氟聚合物事业
部总工程师
Qingwen Meng, Chief Engineer of
Fluoropolymer Division, Juhua Co., Ltd.



《自主可控 PTFE 膜材与全氟滤芯，赋能先进制程国产替代》
Autonomous and controllable PTFE
membrane materials and perfluorinated
filter elements empower domestic
substitution in advanced manufacturing
processes

阙俏颖 飞潮(上海)新材料股份有限公司应用
技术总监
Qiaoyin Que, Director of Application
Technology, Feature-Tec (Shanghai)
Advanced Materials Co., Ltd.



《国内集成电路材料产业现状及发展态势》
Current Status and Development Trend
of China's Integrated Circuit Materials
Industry

王佳 集成电路材料产业技术创新联盟
资深分析师
Jia Wang, Senior Analyst of ICMtia



《06 专项“集成电路关键原辅材料”项目与
标准宣贯》
Promotion and Implementation of
Projects and Standards Under the
06-Major Project — Key Raw and Auxiliary
Materials for Integrated Circuits

叶怀英 浙江巨化股份有限公司高级工程师
Huaiying Ye, Senior Engineer of
Zhejiang Juhua Co., Ltd

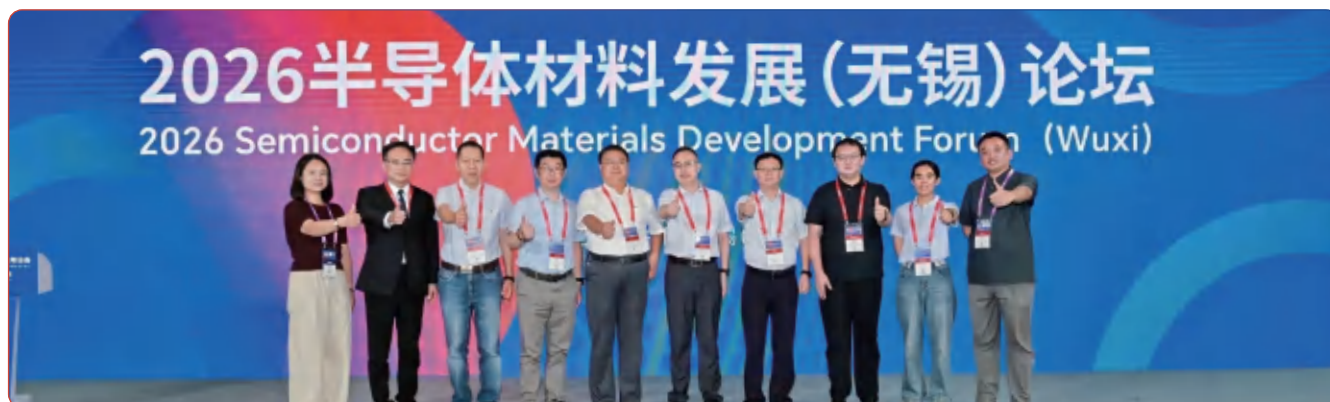
「从国产替代到全球定价」——设备材料零部件投资沙龙 复旦大学校友总会集成电路行业分会

Investment Salon on Equipment, Materials & Components: “From Import Substitution to Global Pricing”
– IC Industry Chapter, Fudan Alumni Association



2026半导体材料发展（无锡）论坛

2026 Semiconductor Materials Development Forum (Wuxi)



● 嘉宾风采 Speakers



主持人:林健 中国电子材料行业协会半导体材料分会秘书长
Moderator: Mr. Jian Lin, Secretary-General of the Semiconductor Materials Branch, CEMIA; Former Chief Expert, CETC 46th Research Institute.



刘锋 中国电子材料行业协会半导体材料分会理事长
Liu Feng, President of the Semiconductor Materials Branch, CEMIA



《应用导向的晶片材料技术》
Technology of Application-oriented Silicon Wafers
李文中 上海合晶硅材料股份有限公司 首席技术官、副总经理
Dr. Wenzhong Li -Chief Technology Officer、Vice General Manager, Wafer Works Co. (Shanghai)



《集成电路大硅片的发展趋势》
Development Trends of Large Silicon Wafers for Integrated Circuit Applications
张俊宝-上海超硅半导体股份有限公司总监
Dr. Junbao Zhang, CTO, Shanghai Advanced Silicon Technology Co., Ltd.



《磷化铟衬底介绍》
Introduction on Indium Phosphide (InP) Substrate
任殿胜 北京通美晶体技术股份有限公司技术总监
Dr. Diansheng Ren, Director of Beijing Tongmei Crystal Technology Co., Ltd. (AXT Inc.)



《高质量大尺寸氧化镓衬底晶圆的进展与挑战》
Progress and Challenges of High-Quality Large-Diameter Gallium Oxide Substrate Wafers
张辉 杭州镓仁半导体有限公司董事长
Mr. Hui Zhang, Chairman, Hangzhou Garen Semiconductor Co., Ltd.



《氮化铝超宽禁带半导体材料发展现状及趋势研究》

Research on Development Status and Trend of Aluminum Nitride Ultra-Wide Bandgap Semiconductor Materials

解楠 中国电子信息产业发展研究院 集成电路研究所 化合物半导体研究室主任
Mr. Nan Xie -Director and Senior Engineer ,
the Compound Semiconductor Research
Office at the Integrated Circuit Research
Institute, China Electronics Information
Industry Development Research Institute.



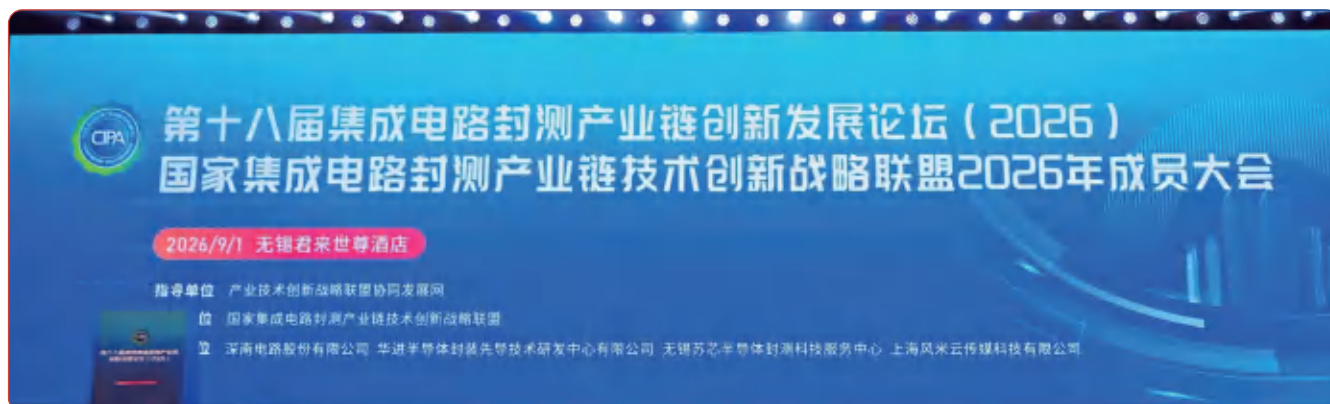
《晶圆级金刚石研究进展》

Research Progress of Wafer-Scale Diamond

兰飞飞-中国电子科技集团公司第四十六研究所研究员、专家

Dr. Feifei Lan, Expert, the 46th Research
Institute of China Electronics Technolo-
gy Group Corporation

CIPA 2026：第18届集成电路封测产业链创新发展论坛
The 18th Integrated Circuit Packaging and Testing Industry Chain Innovation
and Development Forum (CIPA 2026)



● **嘉宾风采**
Speakers



主持人：蔡坚 清华大学 研究员
Moderator: Cai Jian, Researcher,
Tsinghua University



杨之诚 国家集成电路封测产业链技术
创新战略联盟当值理事长
Yang Zhicheng, Rotating Chairman,
National Integrated Circuit Packaging
and Testing Industry Chain Technology
Innovation Strategic Alliance



顾国栋 无锡高新区党工委副书记、
新吴区区长
Gu Guodong, Deputy Secretary of the
Party Working Committee of Wuxi
National Hi-Tech District (WND), Mayor
of Xinwu District



李新男 原中国科学与科技政策研究会副理
事长、原产业技术创新战略联盟协同发
展网理事长
Li Xinnan, Former Vice Chairman of the
China Association for Science and S&T
Policy Research, Former Chairman of
the Collaborative Development
Network of Industrial Technology
Innovation Strategic Alliances



施毅 南京大学微电子学院院长 中国科学
院院士
Shi Yi, Dean, the School of Microelectron-
ics at Nanjing University; Academi-
cian, the Chinese Academy of Sciences



《集成电路前沿进展》
Progresses in Frontiers in Microelectronics
刘胜 中国科学院院士 武汉大学工业科学
研究院执行院长、集成电路学院院长
Liu Sheng, Academician of the Chinese
Academy of Sciences; Executive Dean of
the Wuhan University Institute of
Industrial Science; Dean of the School
of Integrated Circuits



《封装的演进和未来》
Evolution and Future of IC Packaging

杨程 江苏长电科技有限公司科学家
Yang Cheng, Scientist, JCET Group



《AI算力浪潮下的高速接口封装创新与演进趋势》
Trends in innovative high speed-IO packaging driven by AI computing

丁敬峰 通富微电子股份有限公司技术副总
Ding Jingfeng, Tech. VP, TFME



《新时代先进封装发展趋势和策略》
Advanced Packaging Development Trends and Strategies in the New Era

于大全 国家集成电路特色工艺及封装测试创新中心主任 厦门云天半导体科技有限公司创始人
Yu Daquan, Director of the National Innovation Center for Specialized Integrated Circuit Processes and Packaging Testing, Founder of Xiamen Yuntian Semiconductor Technology Co., Ltd.

封测设备与材料创新支撑论坛

Forum on the Innovation in Packaging and Testing Equipment and Materials



● 嘉宾风采 Speakers



主持人：杨剑宏 苏州晶方半导体科技股份有限公司研发部总经理
Moderator: Bryan Yang, R&D General Manager, China Wafer Level CSP Co., Ltd.



《高算力芯片封装产能提升的解决方案》
A Solution to Boost the Packaging Throughput of HPC Chips
郭垒 华海清科股份有限公司CMP事业部总经理
Lei Guo, General Manager of the CMP Division, Hwatsing Technology Co., Ltd.



《半导体光学检测技术创新与国产化突破》
Technological Innovation and Domestic Breakthrough of Process Optical Inspection in the Full Semiconductor
欧阳嘉诚 珠海诚锋电子科技有限公司产品总监
Owen, Product Director, Zhuhai Chengfeng Electronic Technology Co., Ltd.



《AI 趋势下 FC-BGA 产品技术演进方向》
The technological evolution direction of
FC-BGA packaging substrate under the
AI trend

李玉龙 广州广芯封装基板有限公司
前沿技术研发经理
Yu Long Li, Advanced Technology R&D
Manager, GreatTech Substrates Co., Ltd



《东精精密 (Accretech) 三维封装工艺及散
热技术专项技术更新》
Accretech technical update for 3D package
process and heat dissipation technology

白建星 东精精密设备(上海)有限公司市场部
Jianxing Bai, Marketing Planning &
Information Dept, ACCRETECH (CHINA)
CO., LTD



《东精精密 (Accretech) 三维封装工艺及散
热技术专项技术更新》
Accretech technical update for 3D package
process and heat dissipation technology

陆振洲 东精精密设备(上海)有限公司市场部
Zhenzhou Lu, Marketing Planning &
Information Dept, ACCRETECH (CHINA)
CO., LTD



《再定义高功率ATC:AI测试的热控未来》
Rethinking High-Power ATC: Thermal
Control for the AI Test Era

巩 钰 天津金海通半导体设备股份有限公
司技术副总
Yu Gong, VP of Technology, JHT Design
Co., LTD.



《电子封装关键材料的国产化替代》
The Domestic Substitution of Key
Electronic Packaging Materials

朱顺利 晶丰电子封装材料(武汉)有限公司
常务副总裁
SHUNLI ZHU, Deputy Vice President, EP
Materials (Wuhan) Co. Ltd.



《半导体先进封装材料与工艺协同创新》
Co-innovation of Materials and
Processes for Advanced Semiconductor
Packaging

胡彦杰 钢泰公司中国区技术经理
Leo Hu, Country Technical Manager -
China, Indium Corporation

AI 时代先进封装技术协同研发论坛

Forum on the Collaborative R&D in Advanced Packaging Technologies for the AI Era



● 嘉宾风采 Speakers



主持人：何洪文 华进半导体封装先导技术研发中心有限公司代总经理
Moderator: Hongwen He, CEO, National Center for Advanced Packaging Technology



致辞嘉宾：徐冬梅
Welcome Address: Dongmei Xu



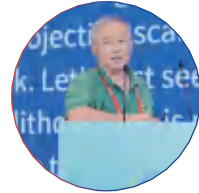
《先进封装驱动智能世界发展》
AD PKG Drives AI Development
党超强 华天科技总部技术市场中心
TPM经理
Leo, TPM, Tianshui Huatian Technology Co., Ltd.



《中微卓越的产品解决方案，助力先进封装良率新高度》
AMEC Superior Product Solution Empowered Innovation For Advanced Packaging Yield Enhancement
邵利 中微半导体设备(上海)股份有限公司
先进封装商业拓展资深总监
Li Tai, Sr. Director of Advanced Packaging Business Development, Advanced Micro-Fabrication Equipment Inc. China



《AI时代光互连与光电共封技术》
Optical Interconnection and OE Co-packaging Technology in the AI Era
刘丰满 华进半导体封装先导技术研发中心有限公司副总经理
Fengman Liu, VP, NCAP



《先进封装中大面积模块的光刻技术》
Photolithography Technology for Large-Area Modules in Advanced Packaging
龚里 苏斯贸易(上海)有限公司总经理
Li Gong, General Manager, Suss MicroTec(shanghai) LTD



《AI 赋能先进封装设计新范式:2.5D/3DIC EDA 全流程STCO协同创新》
AI-Empowered New Paradigm for Advanced Packaging Design: Full-Flow STCO Collaborative Innovation for 2.5D/3D IC EDA

吴明辉 珠海硅芯科技有限公司高级产品研发工程师
Minghui Wu, Senior Product Development Engineer, Zhuhai Silicon Chip Technology Ltd.



《先进封测,精准感知——打造传感器封测技术新高地》
Advanced Packaging & Testing, Precision Sensing— Forge a New High Ground in Sensor Packaging & Testing Technology

龚黎泉 上海共进微电子有限公司市场销售总监
Jiegfried Gong, Marketing & Sales Director, Shanghai Gongjin Microelectronics Technology Co., Ltd.



《国家智能传感器创新中心特色三维异质晶圆工艺》
Characteristic 3D Heterogeneous Wafer Process, National Innovation Center for Intelligent Sensors

潘代强 上海芯物科技有限公司中试线负责人
Ted, Head of Pilot Line, Siwave, Inc.

封测市场供应链安全与跨界协同论坛

Forum on the Supply Chain Security and Cross-Industry Collaboration in the Packaging and Testing Market



● 嘉宾风采 Speakers



主持人: 高瑞锋 华天科技技术市场中心总监
Moderator: GAO Ruifeng , Marketing Director, HT-Tech



《人工智能时代的功率半导体与集成技术》
Power Semiconductor and Integration Technology in the AI Era

刘国友 中车科学家、功率半导体与集成技术全国重点实验室副主任、西南交通大学集成电路学院 副院长
Liu Guoyou , CRRC scientist, Deputy Director, National Key Lab of Power Semiconductor and Integration; Associate Dean, School of Integrated Circuits, Southwest Jiaotong University



《AI应用场景需求推动封装多样化》
AI application scenario requirements push various packaging

李卫东 锐杰微科技CMO



《临港新片区集成电路产业发展介绍》
Introduction to the IC Industry Development in Lingang Special Area

郭延齐 临港新片区企服中心企业服务办主任



《破解先进封装 VOC 治理痛点,LACO高效吸附低温催化降解一体化解决方案》
Solving the pain points in advanced packaging VOC management LACO high-efficiency adsorption and low-temperature catalytic degradation integrated solution

金华 上海揽臻环保科技有限公司技术总监
Jin Hua, Technical Director, Shanghai Lanzhen Environmental Protection Technology Co., Ltd.



《面向先进封装的超声检测技术创新与国产突破》

Innovations and Independent Breakthroughs of Ultrasonic Inspection in Advanced Packaging

游胜卫 上海骄成超声波技术股份有限公司销售总监
You Shengwei, Sales Director, SBT Ultrasonic Technology Co., Ltd.



《核心装备自主可控:晶圆传送机械手国产化实践与进程》
Self-controllable Core Equipment: Practice and Development of Domestic Wafer Transfer Robots

靳文 泓沚(苏州)半导体科技有限公司CMO
Jin Wen, CMO, Honghu (Suzhou) Semiconductor Technology Co., Ltd.



《多品类晶圆工艺集成下的封测供应链: MEMS/BCD/硅光跨界协同破局思路》
Packaging & Testing Supply Chain Under Multi-Type Wafer Process Integration: MEMS, BCD and Silicon Photonics

邓彤 广州增芯科技有限公司市场总监
Aileen Deng , Marketing director, Guangzhou Zen Semiconductor Corporation